

# Some FPGA SoC Applications and Trends in Advanced System On Chip

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# Outline of Presentation

## (1) SoC Applications

- Context
- Why FPGA Technology?
- The Options?
- Two Case Studies
- Summary
- Short stretch break
  - 5 minutes



# Outline of Presentation

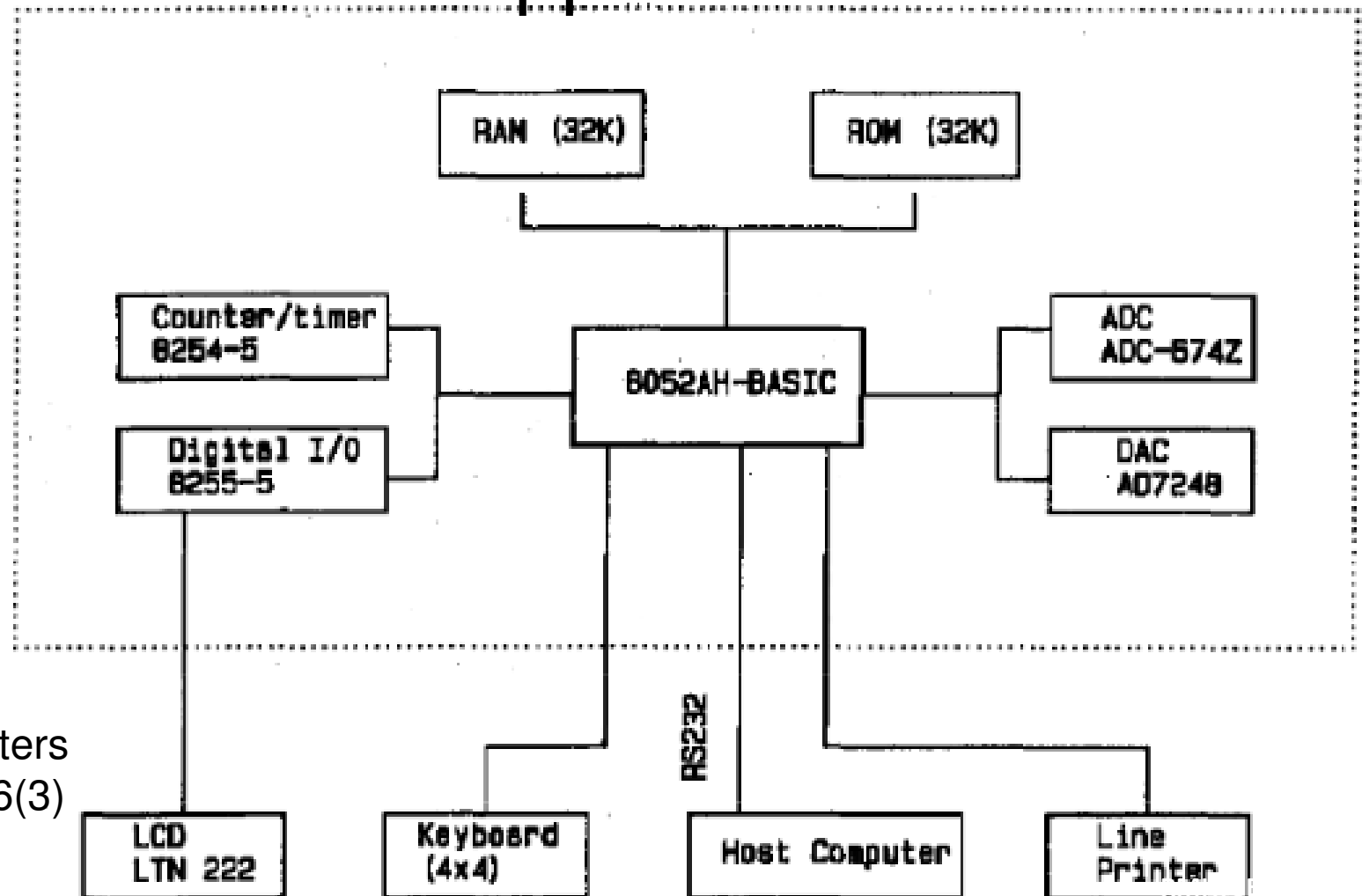
## (2) SoC Trends

- What is a SoC?
- Future Trend Drivers
- 3D Chip Stacking
- Current SoC tools
- Conclusions



# Scope – Instrumentation

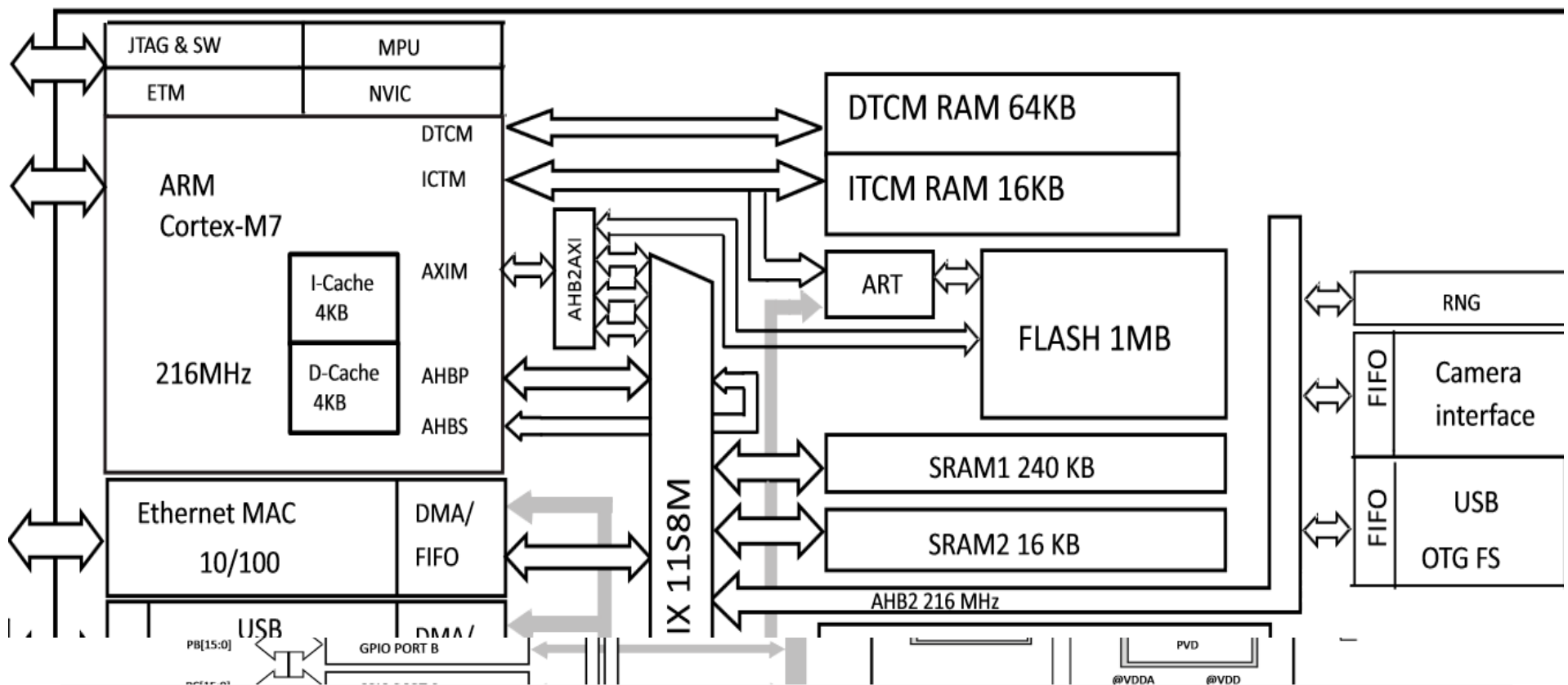
- The “traditional” approach



Source: Computers  
& Chemistry, 16(3)  
July 1992

# Scope – Instrumentation

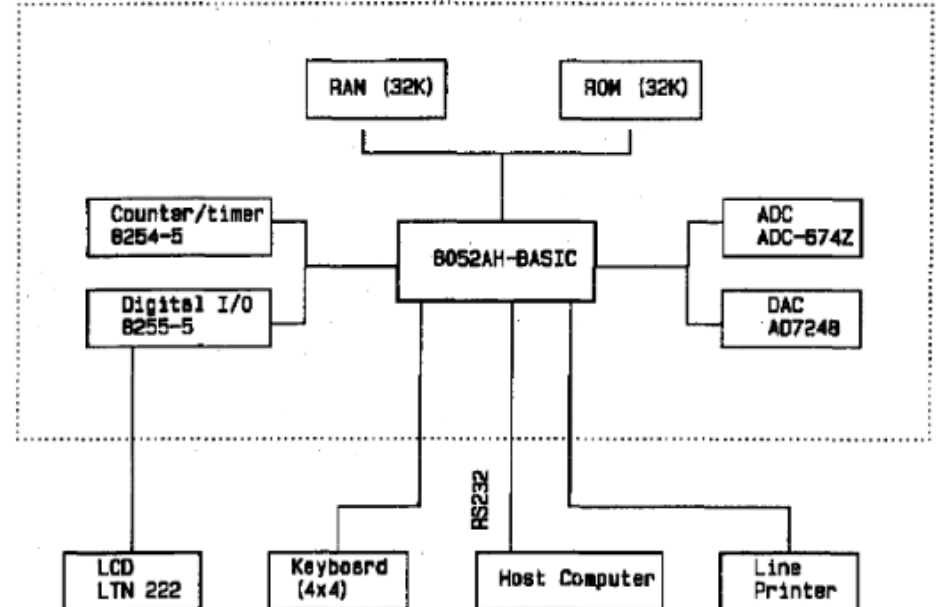
- How much has really changed?



Source: STMICRO ARM® Cortex®-M7 core datasheet

# Context – the problem

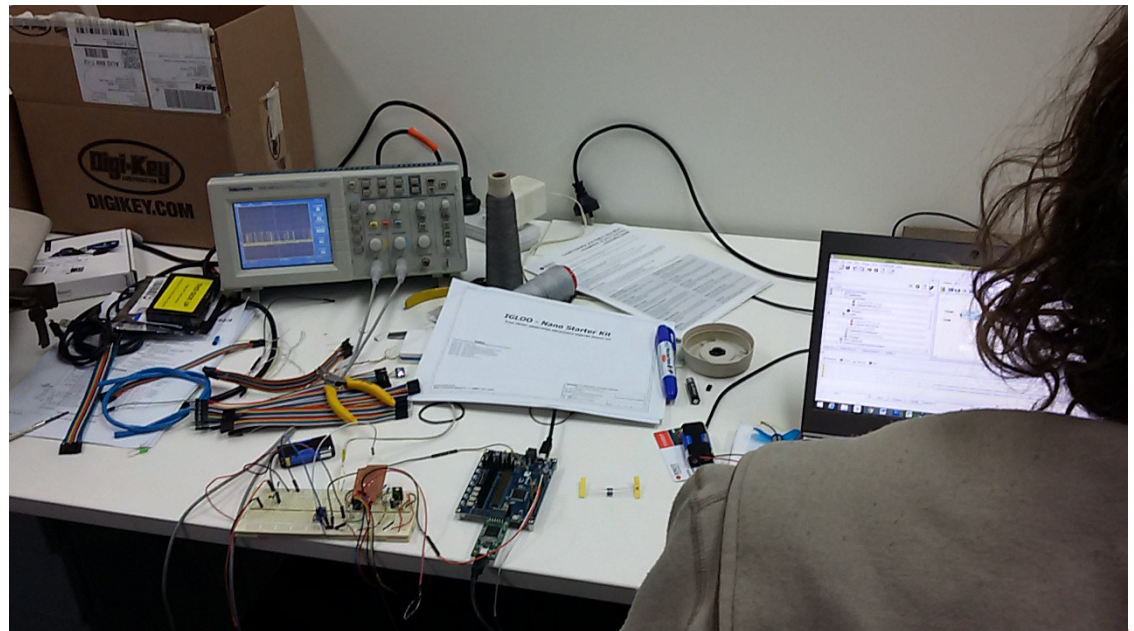
- Data acquisition & storage
- Local control
- Local processing
  - Filtering
  - Formatting
- Data transfer
  - Protocols
  - Error detection/correction



# Embedded Sensors

## – the challenges

- Sensor Complexity
- Noise
- Flexibility
- Size
- **Power**



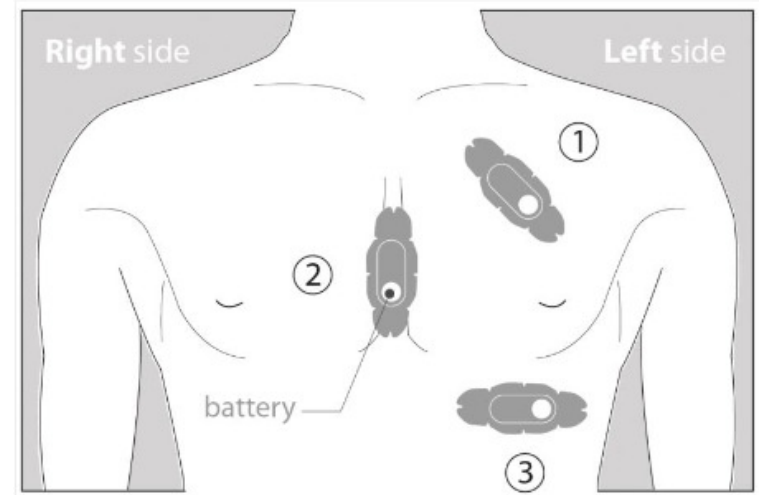
# Embedded Sensors– the issues

The Issues	Some solutions
<b>Sensor Complexity</b> e.g., physiological monitoring	High sensitivity ADC, variable resolution, sensor control and timing
<b>Noise</b> – e.g., common mode interference	Digital interfaces - $\Sigma\Delta$ ADC systems
<b>Flexibility</b> – e.g. multiple protocols	In-field and post manufacture programmability,
<b>Size</b> personal interfaces	Beyond SMD, SOIC, SOT Flexible substrates, implanted electronics
<b>Power</b>	Flash-based devices (e.g., IGLOO)



# Why FPGA Technology?

- Performance
  - exploiting hardware parallelism
  - can do more per clock cycle
- Time to Market
  - flexibility and rapid prototyping capabilities
- Cost
  - low NRE compared to ASIC
  - (But) higher compared to microprocessor
- Power
  - Parallel operation with lower clock rates can reduce power
  - Ability to “sleep” when inactive



[http://www.vitalconnect.com/upload/Documents/AutomatedPrediction\\_2014\\_IEEE\\_published.pdf](http://www.vitalconnect.com/upload/Documents/AutomatedPrediction_2014_IEEE_published.pdf)

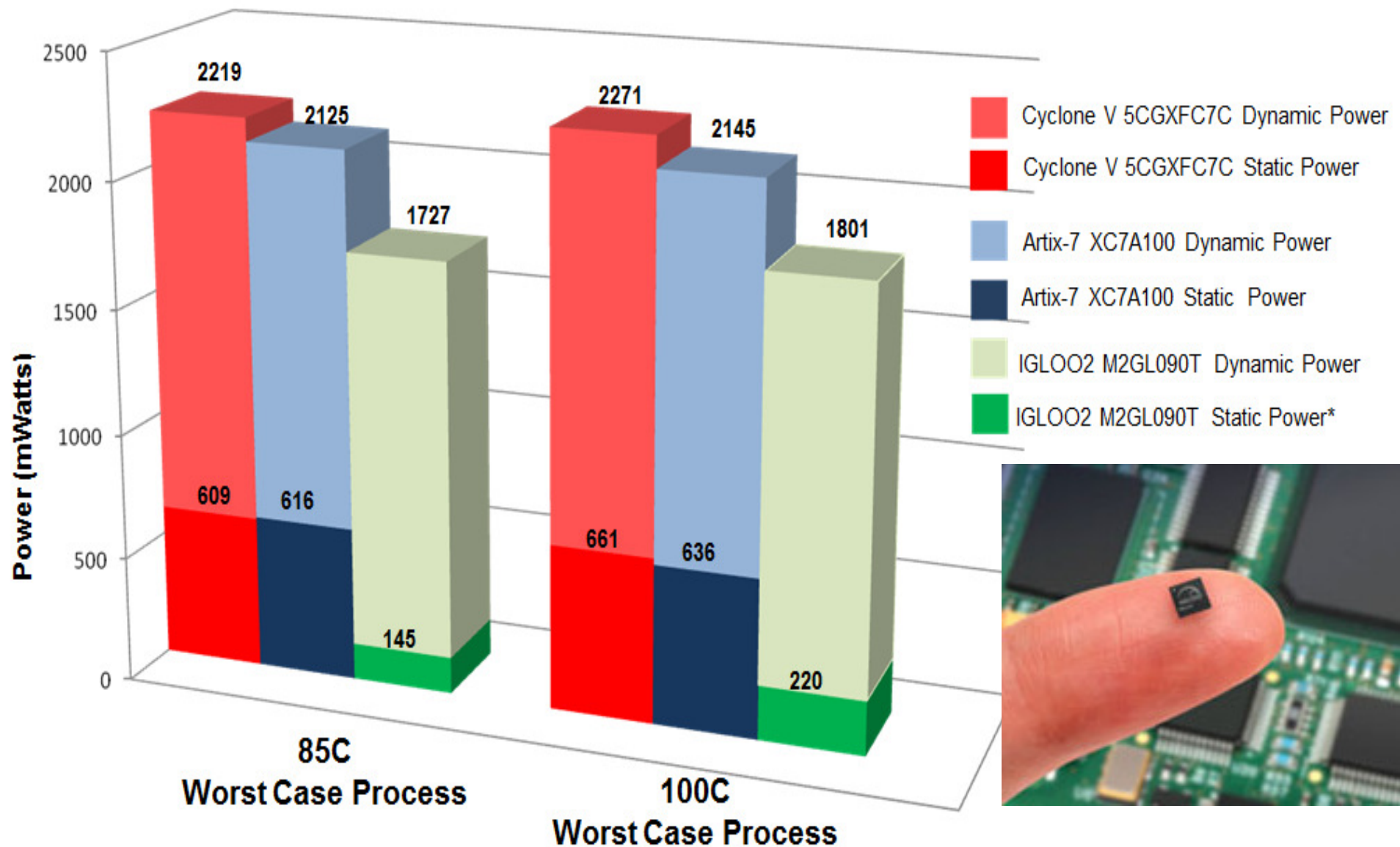
# The Options?

- The “usual suspects”
  - Xilinx, Altera
  - tend to be focusing on high performance & DSP processing
- Smaller players – e.g. MicroSemi starting to offer system on chip
  - Low power
  - Integrated functions (e.g. analog)



Louis Renault – Casablanca 1942

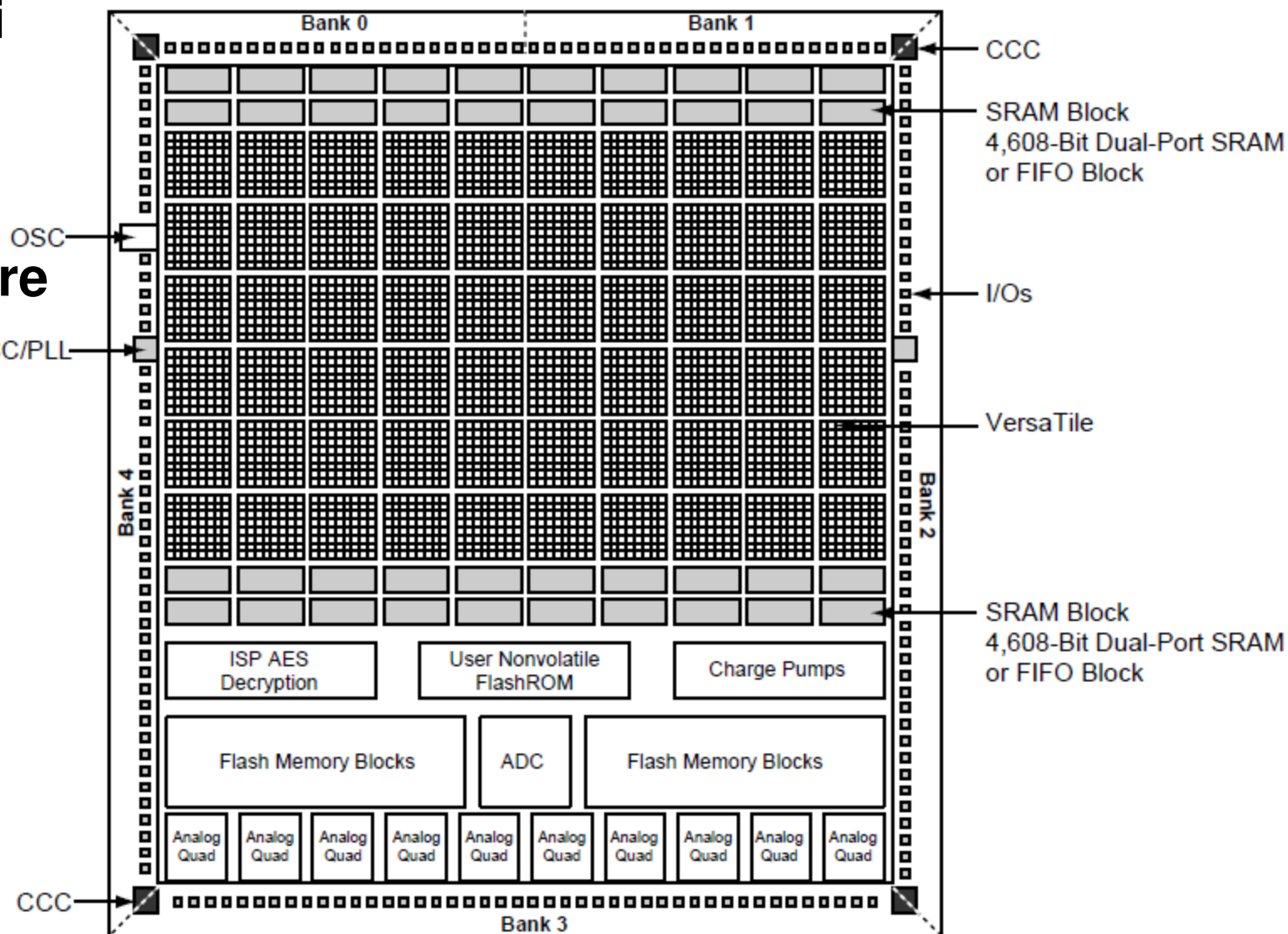
# SoC – Power Considerations



# Small SoC Features

**MicroSemi**  
***Fusion*®**

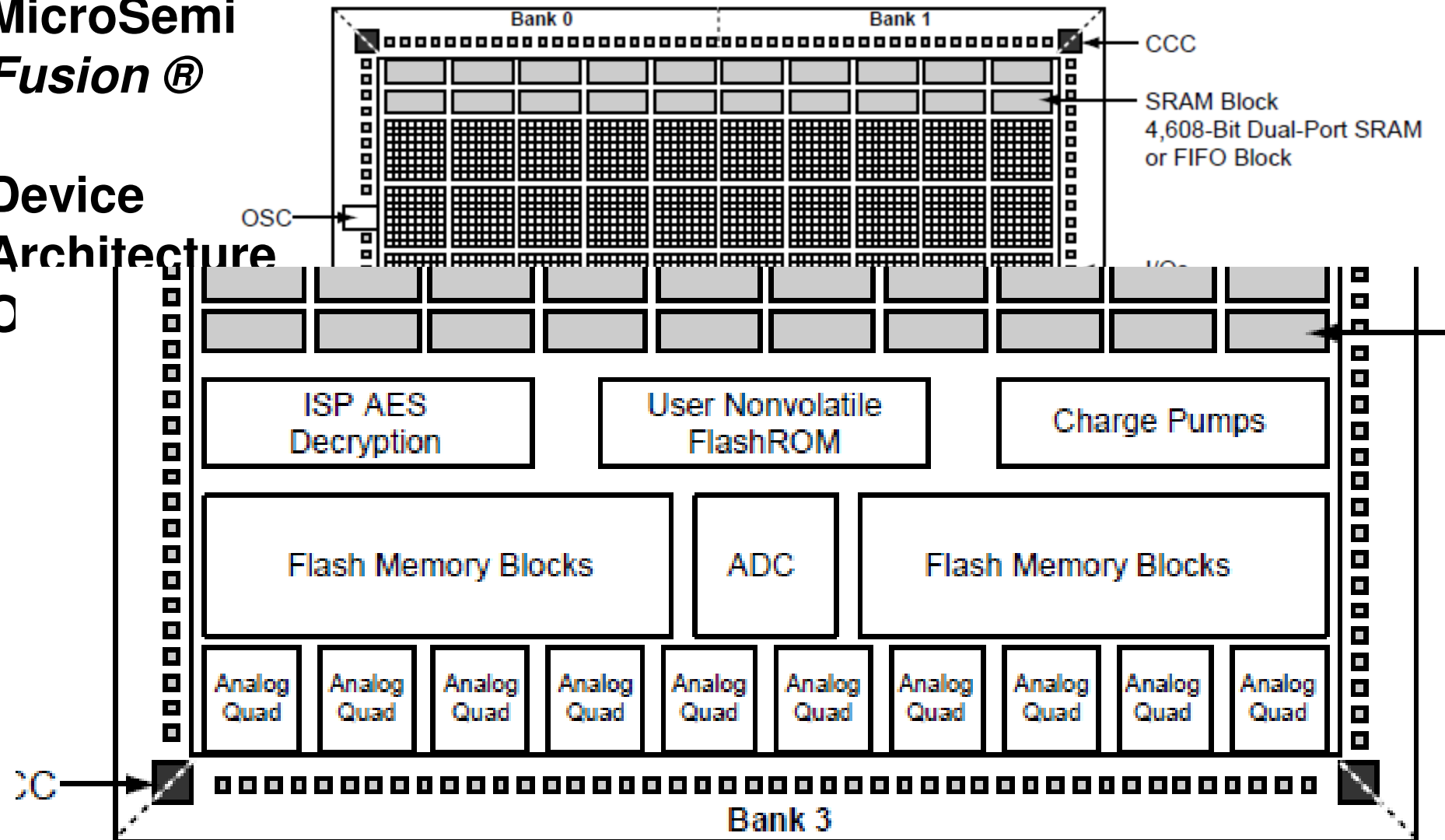
**Device**  
**Architecture**  
**Overview**

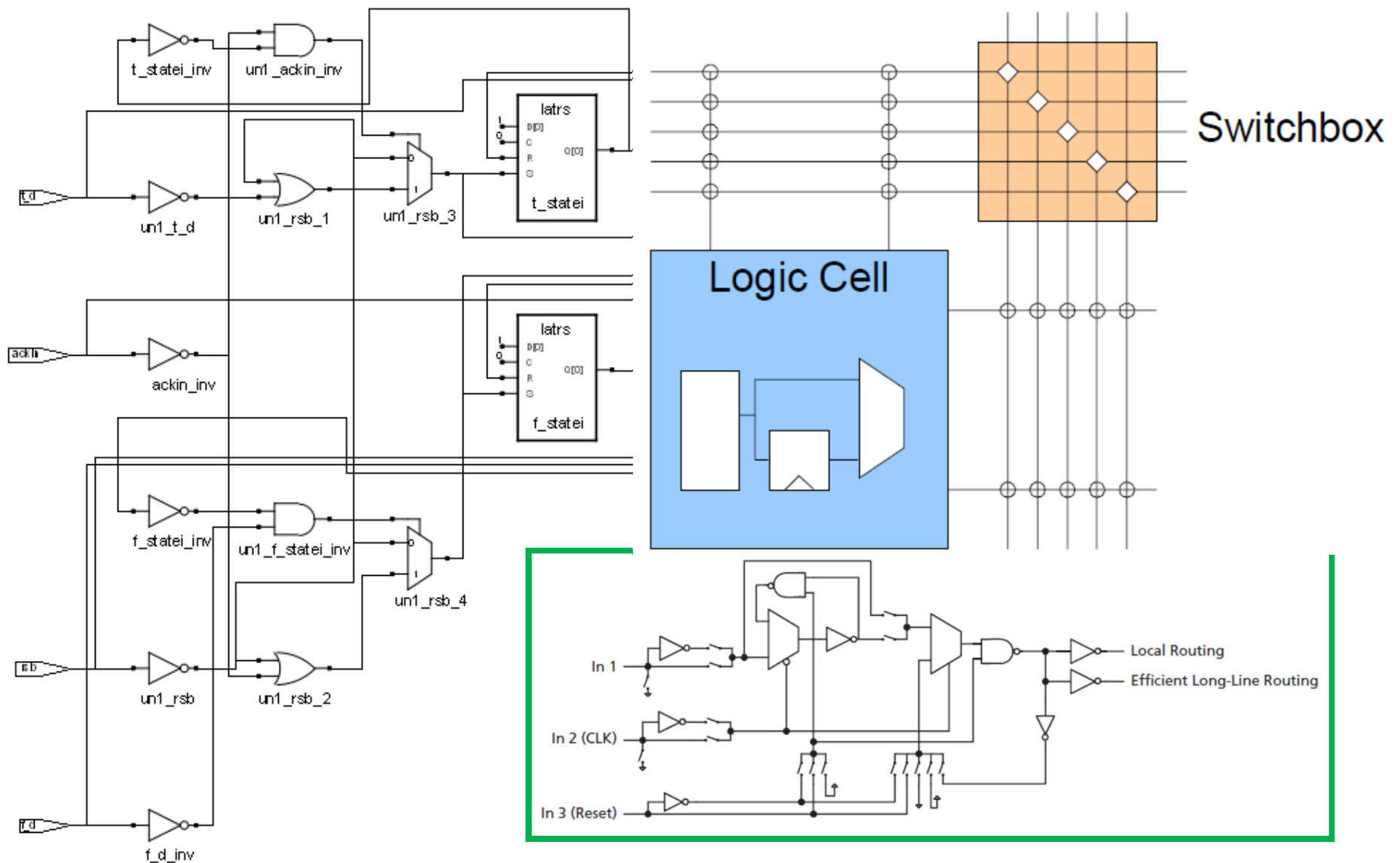


# Small SoC Features

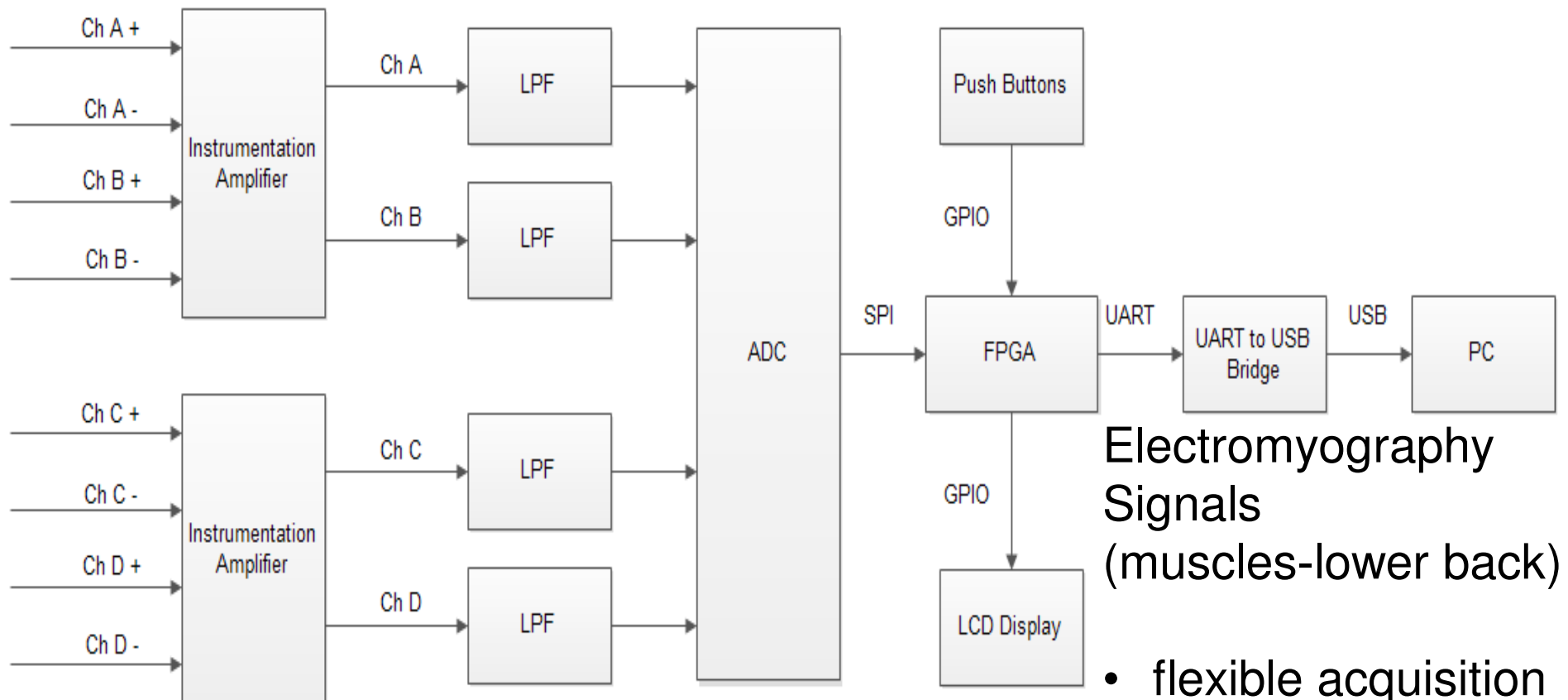
**MicroSemi**  
***Fusion***®

**Device**  
**Architecture**





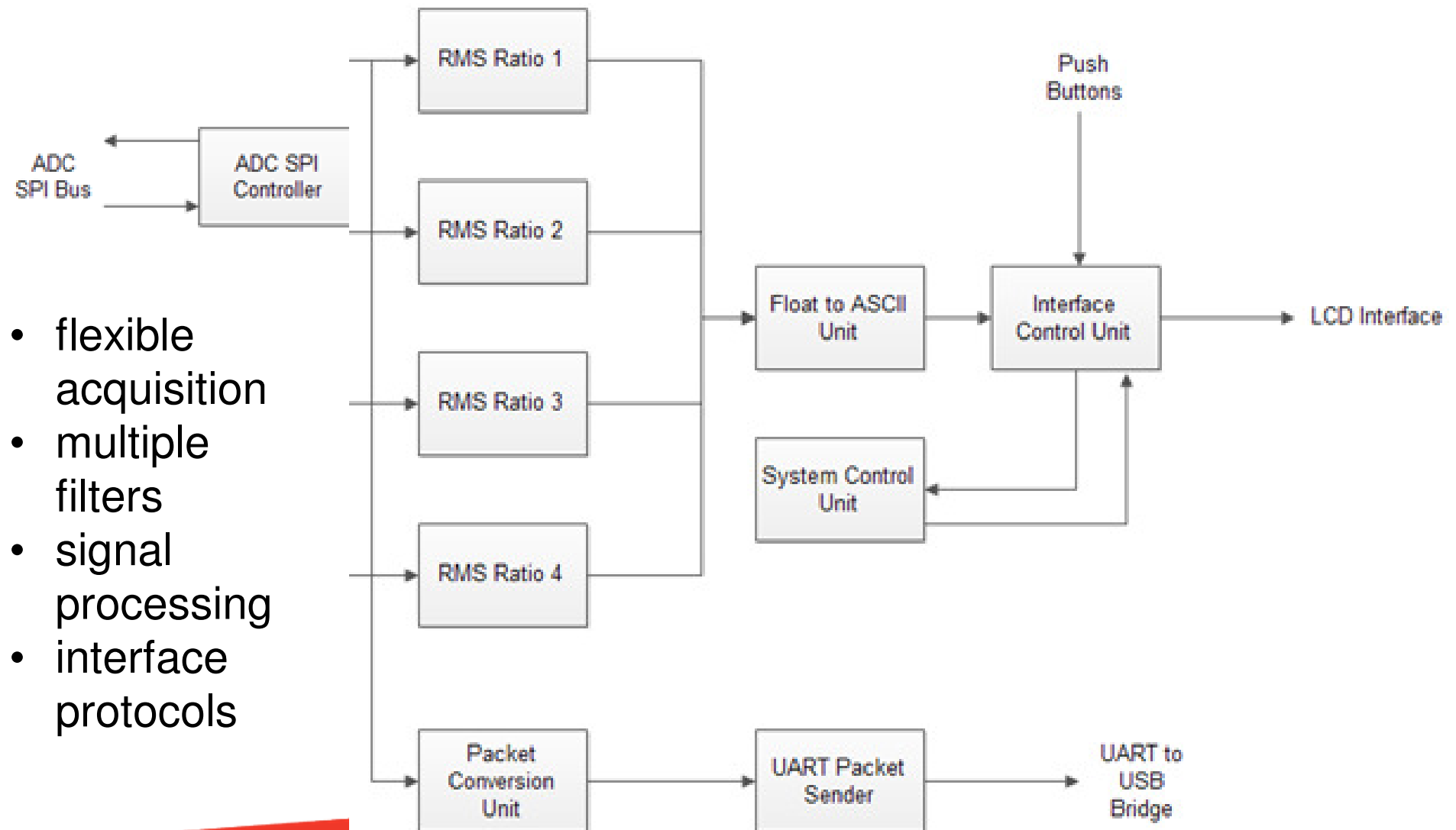
# Case Study 1 – EMG Monitor



Electromyography  
Signals  
(muscles-lower back)

- flexible acquisition
- multiple filters
- signal processing
- interface protocols

# Case Study 1 – EMG Monitor

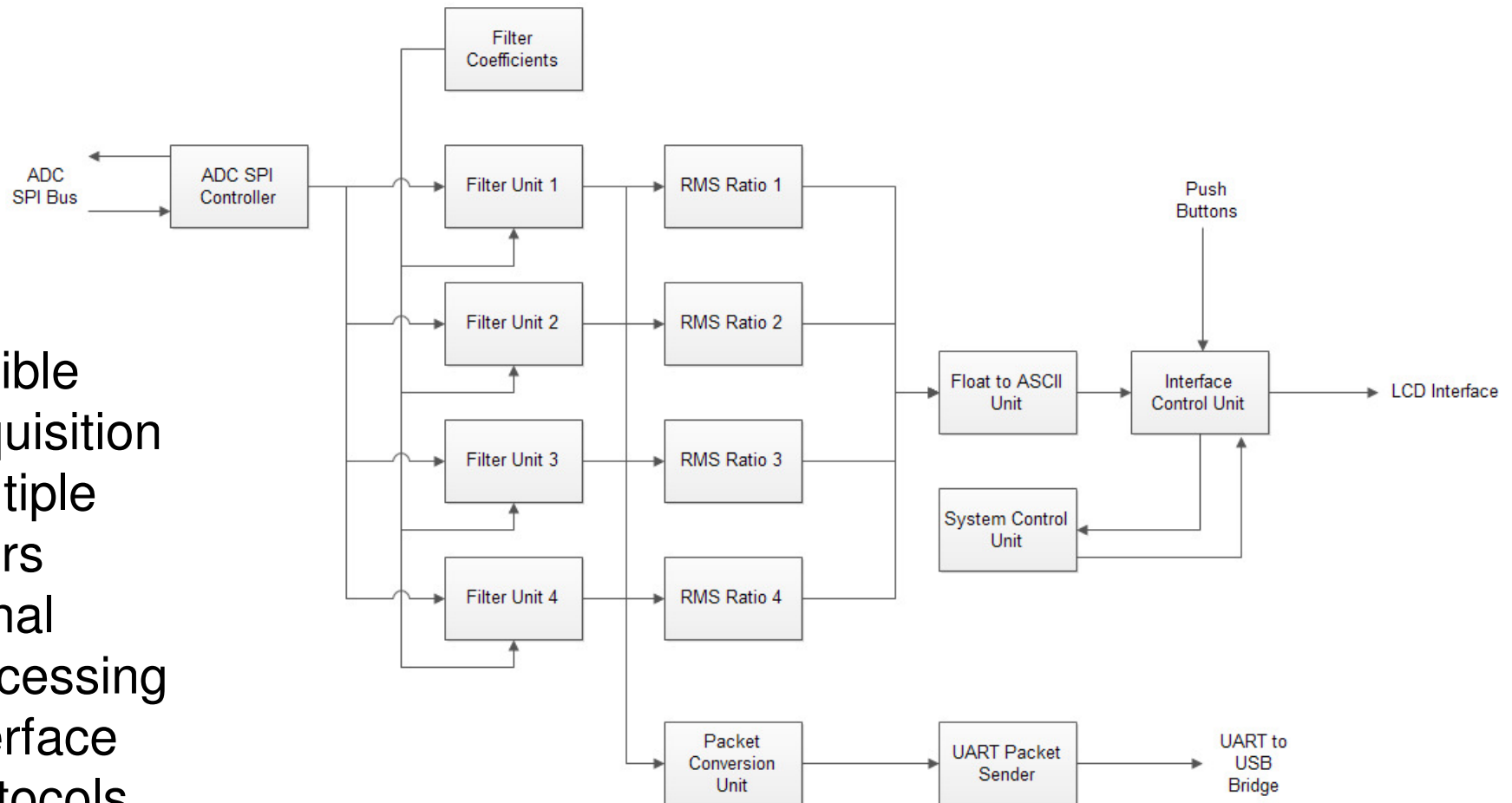


- flexible acquisition
- multiple filters
- signal processing
- interface protocols

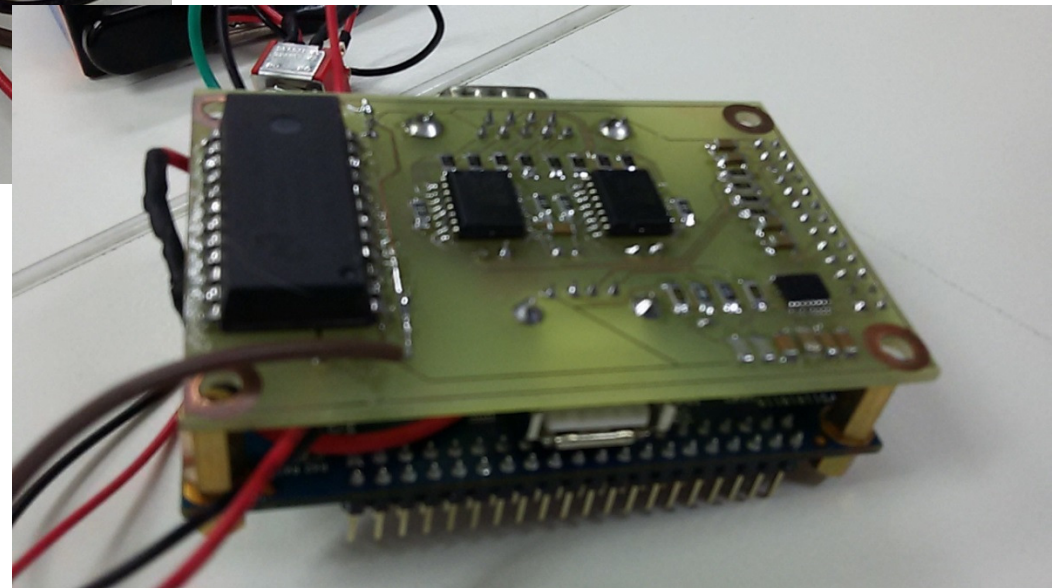
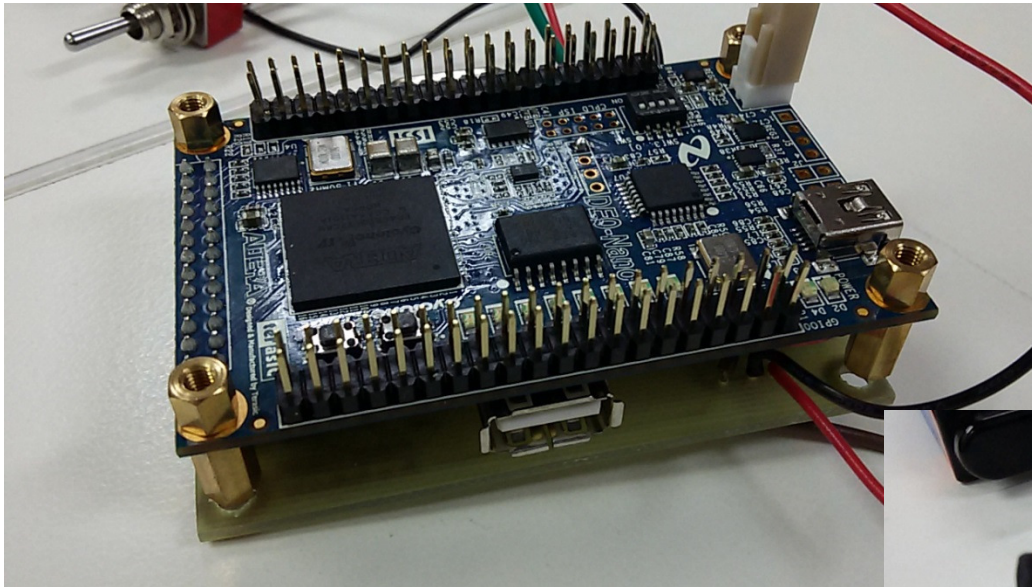


# Case Study 1 – EMG Monitor

- flexible acquisition
- multiple filters
- signal processing
- interface protocols

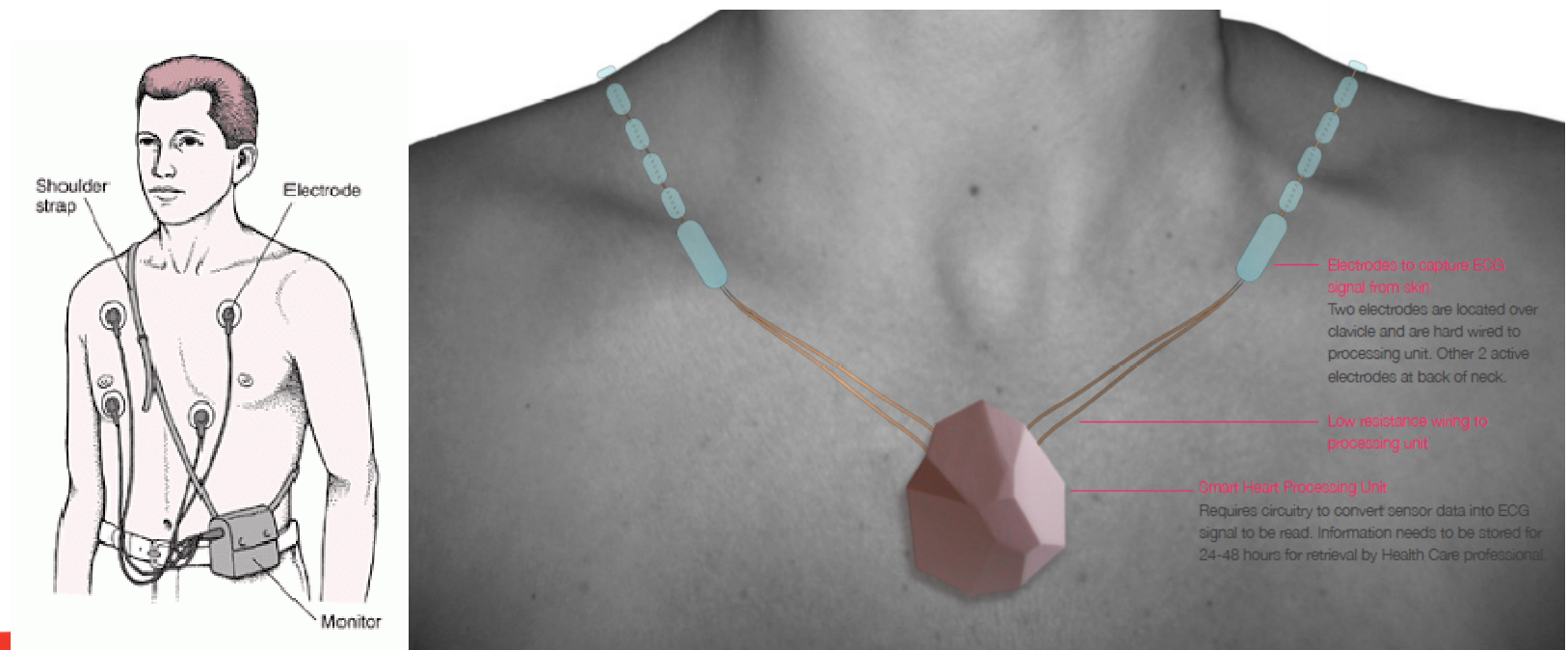


# Case Study 1 – EMG Monitor




# Case Study 2 – “Smart Heart” - miniaturization

- Continuous monitoring for people at risk of cardiac event
- Necklace stores 24-48 hours of ECG data for download and analysis by healthcare professional
- Wearable device that is comfortable and aesthetically desirable

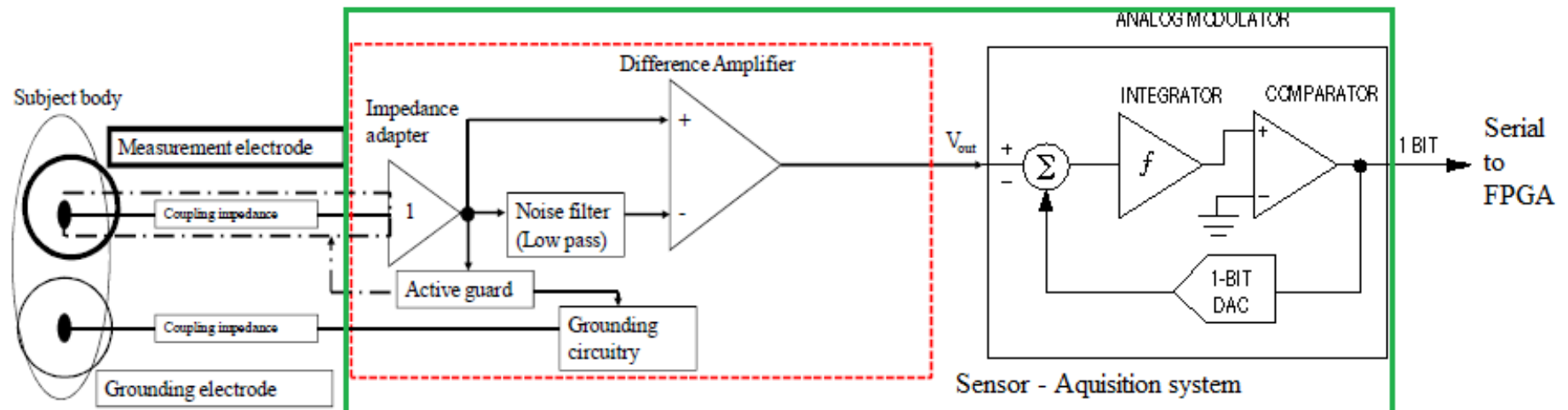


## Case Study - Smart Heart

- Initially intended to record low noise high resolution ECG signal
  - Applicable to a number of different low signal body sensors (ECG, temp, etc.)
  - low powered – ideally, support monitoring of ECG signal over several days
  - Compact, non-invasive implementation, compatible with woven and other fabric holters.
- 

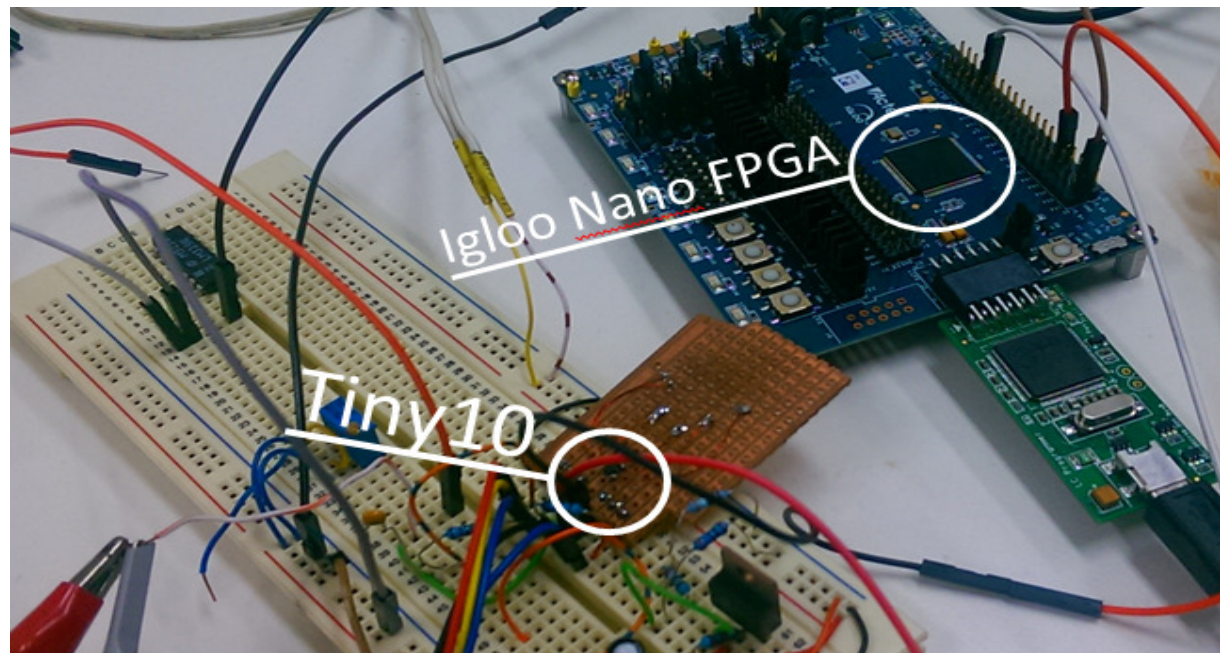
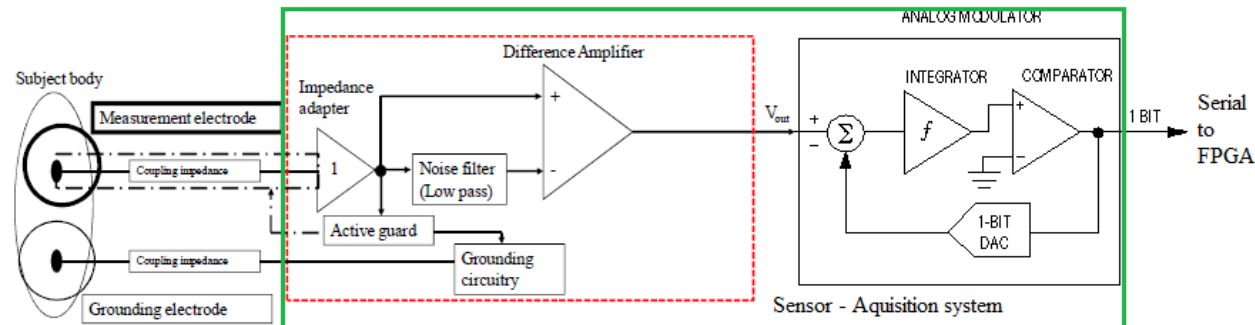
# Case Study – “Smart Heart”

- Front-end microprocessor (ATTiny)
- Backend FPGA
  - Multi-channel signal processing
  - Protocol assembly

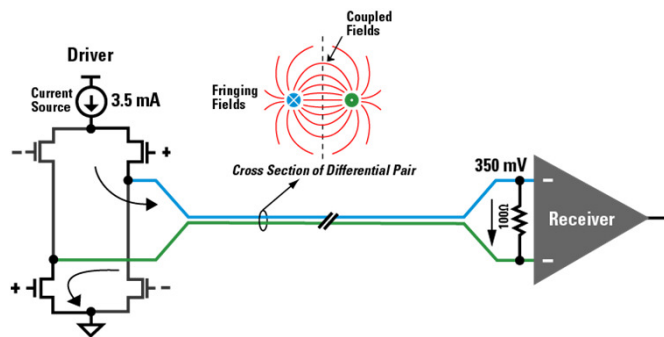




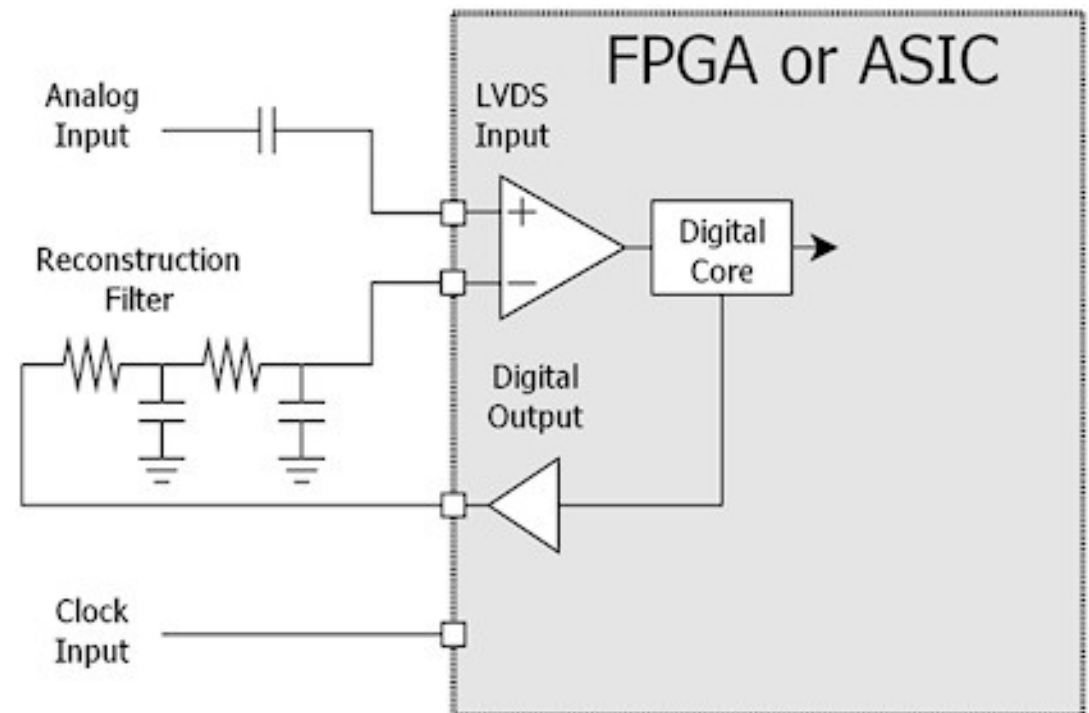
# Case Study – “Smart Heart”



# An Aside: Interface “Tricks”



[http://en.wikipedia.org/wiki/Low-voltage\\_differential\\_signaling](http://en.wikipedia.org/wiki/Low-voltage_differential_signaling)



- “All-Digital” ADC
  - e.g. 11 bits resolution 20 kHz bandwidth
  - 14 bits over 500 Hz ( $\cong 61\mu\text{V}$  with 1V reference)
  - <http://www.stellamar.com/products.shtml#adc>

# Another Aside:

## Effect of Description on Performance

- Case study – two description styles
  1. Merged synchronous-combinational
  2. Separate synchronous-combinational
- Identical functional outcome
  - 15% lower delay along critical paths





```

always @(posedge System_Clock) begin
    //Counter_Preload, Restart_Counter, Cycle_Counter
    case(trigger)
        2'b00: begin //continue, nothing found
            Restart_Counter <= 1'b0;
            Counter_Preload <= Counter_Preload;
        end
        2'b01: begin //edge found inc/dec counter preload
            Restart_Counter <= 1'b1;
        end
    //always queue counter to edge.
        Cycle_Counter <= 1'b0;
        if(!Cycle_Counter) begin
            // edge found but counter unfinished.
            if (Counter_Preload > Pre_Low)
                Counter_Preload <= Counter_Preload - 1;
            else
                Counter_Preload <= Counter_Preload;
            end else begin
                if (Counter_Preload < Pre_High)
                    Counter_Preload <= Counter_Preload + 1;
                else
                    Counter_Preload <= Counter_Preload;
            end
        end
    end
end

```

```

2'b10: begin
    //counterOVF
    //inc count start counter again
    Cycle_Counter <= Cycle_Counter + 1;
    Restart_Counter <= 1'b1;
    Counter_Preload <= Counter_Preload;
end
2'b11: begin
    //continue, clocks synced
    Restart_Counter <= 1'b1;
    Counter_Preload <=
Counter_Preload;
    end
Endcase

```

**Timing Result:**  
**37MHz**

```
wire [9:0] SDMCountInc;  
wire [9:0] SDMCountDec;  
wire [9:0] preloadSEL;  
wire [9:0] counterPreLoadIn;  
wire resetCycleCountIn;
```

```
always @(posedge System_Clock) begin  
    Counter_Preload <= counterPreLoadIn;  
    ResetCycleCounter <= resetCycleCountIn;  
end
```


Clocked components

```
assign preloadLow = (Counter_Preload < Pre_Low);  
assign preloadHigh = (Counter_Preload > Pre_High);  
assign SDMCountDec = (preloadLow)? Pre_Low :Counter_Preload - 1;  
assign SDMCountInc = (preloadHigh)? Pre_High :Counter_Preload + 1;  
assign preloadSEL = (!Cycle_Counter)? SDMCountDec: (Cycle_Counter == 1)? SDMCountInc:  
preloadSEL;  
assign counterPreLoadIn = (edgeFound_assessPreload)? preloadSEL:counterPreLoadIn;  
assign resetCycleCountIn = (edgeFound_assessPreload)? 1'b1: 1'b0;
```

Combinational  
components

## Timing Result: 43MHz

# Summary

- Meeting Performance, Time to Market and Cost targets has tended to mean a micro-processor implementation, BUT...
  - FPGA devices are becoming small, low power and mixed signal
  - As long as hardware parallelism is available then performance can be many times better than DSP
  - Added bonus of flexibility
  - Still have to be careful about description style
- 

# Some FPGA Applications and Trends in Advanced System On Chip



Take a short break  
(5 minutes)

# Outline of Presentation

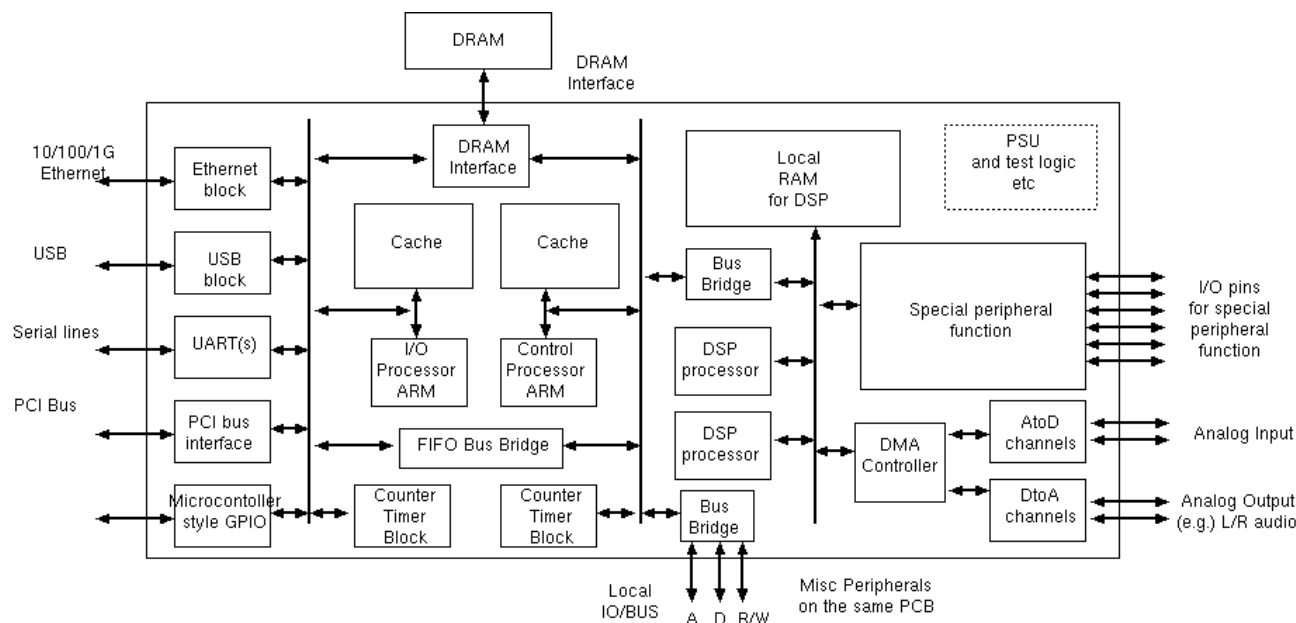
## (2) SoC Trends

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- Future Trend Drivers
- Current SoC tools
- 3D Chip stacking
- Conclusions



# Scope

- Recent SoC trends
- 3D Hardware Trends
- Design abstractions for SoC models



**Definition:**  
A “system” includes a microprocessor, memory and peripherals.

## Caveat

- “It's tough to make predictions, especially about the future.”

*Yogi Berra (b. 1925),  
former American Major League Baseball  
catcher, outfielder, and manager.*



# Trends: UBM Tech®

## 2014 Embedded Market Study

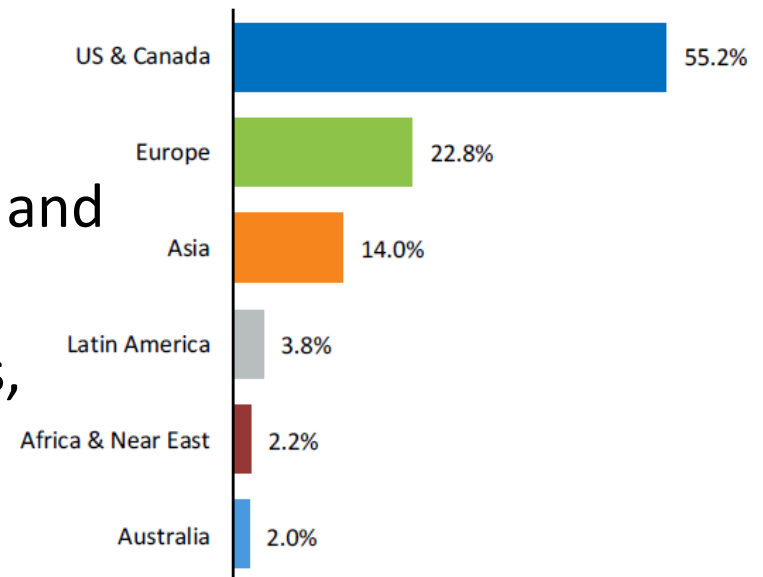
- UBM Tech (embedded magazine)
  - conducts annual **online** survey of worldwide embedded systems markets

- types of technology used
- embedded development process and tools,
- applications, methods/ processes,
- operating systems
- chips, technology and brands

– trended over three to five years.

– **WARNING: most focus is on United States**

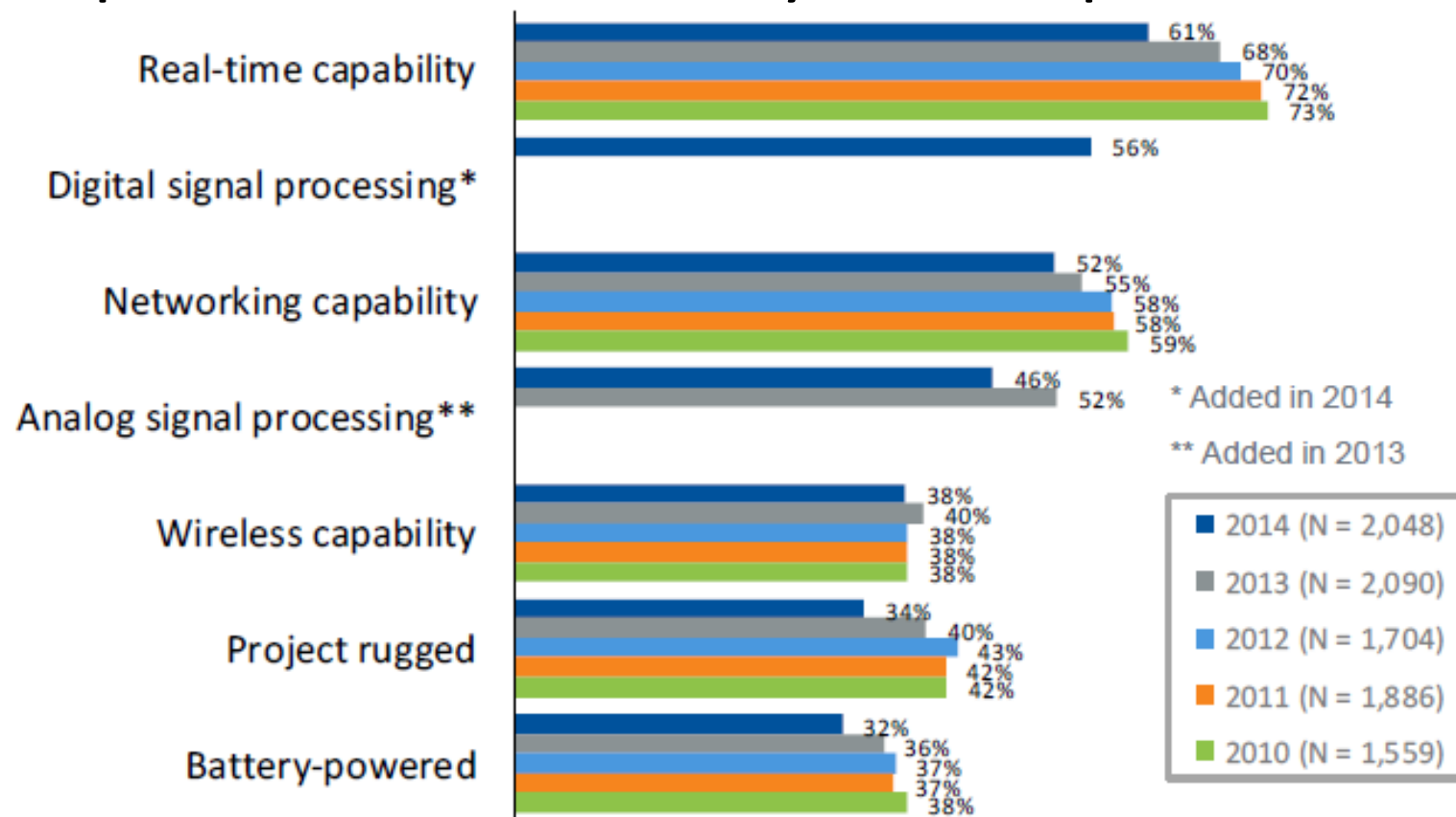
– <http://bd.eduweb.hhs.nl/es/2014-embedded-market-study-then-now-whats-next.pdf>





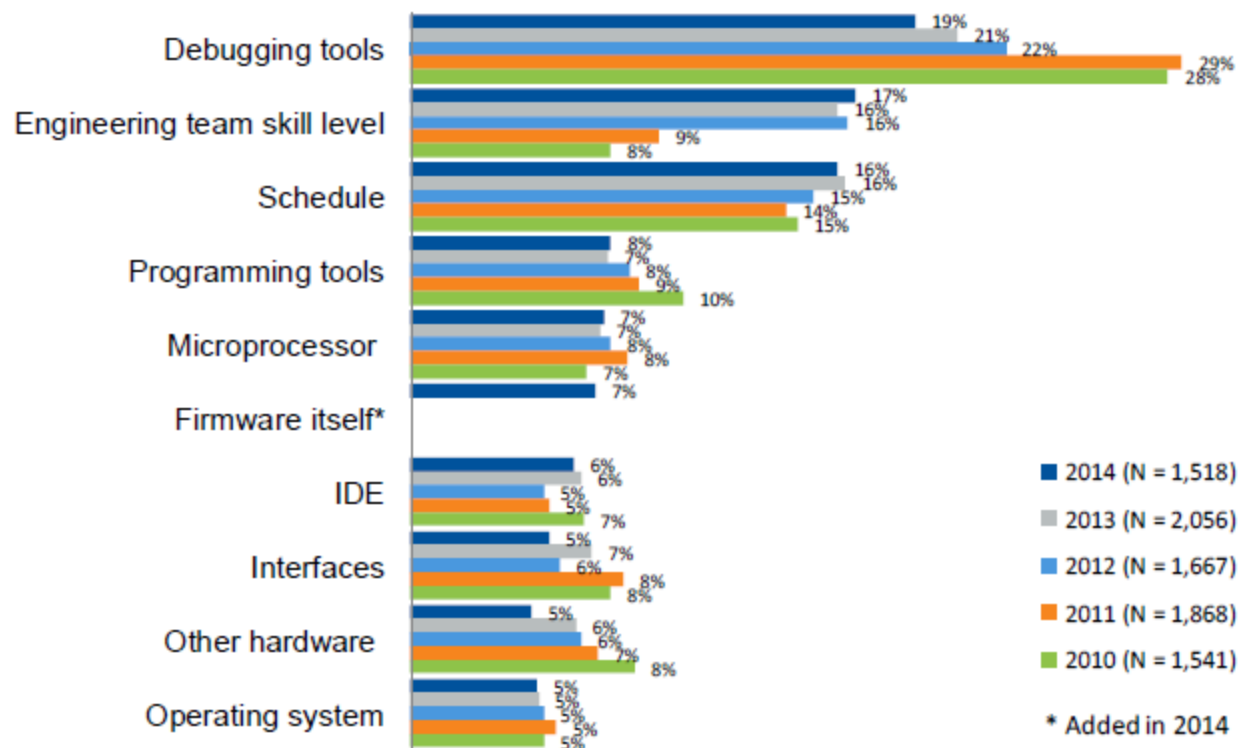
# 2014 Embedded Market Study

- Important Embedded System Capabilities



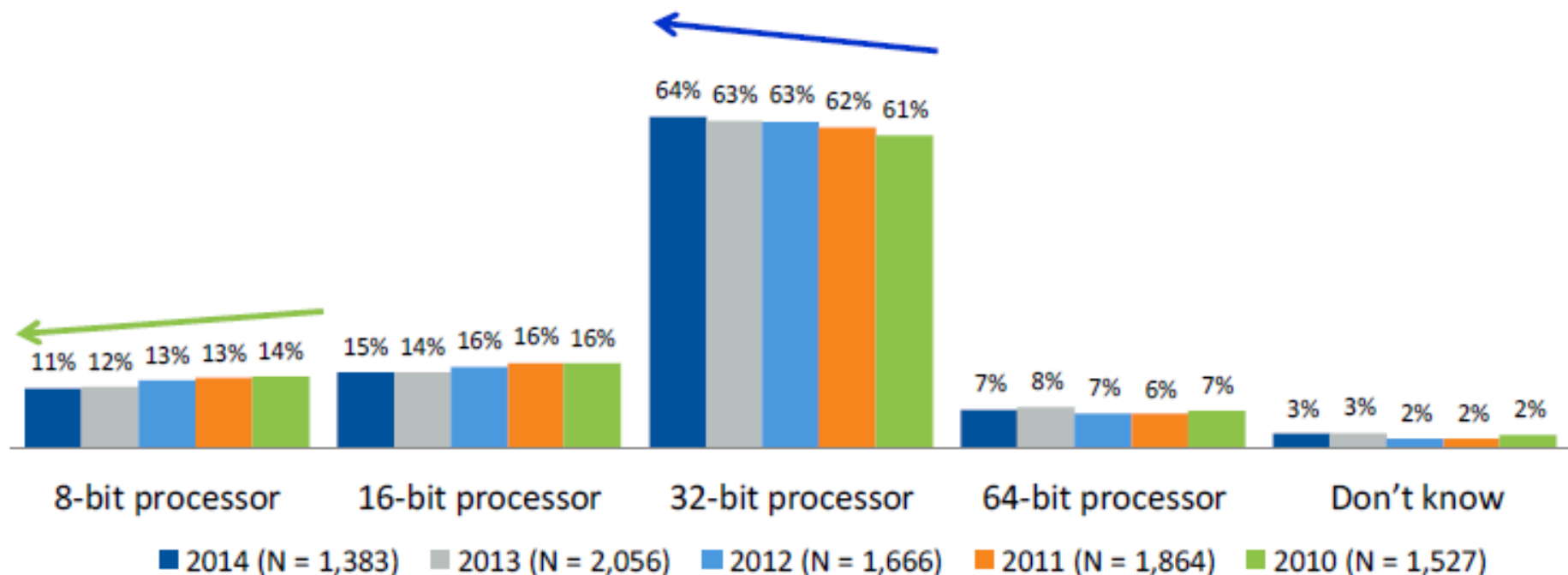
# 2014 Embedded Market Study

- If you could improve one thing about your embedded design activities, what would it be?



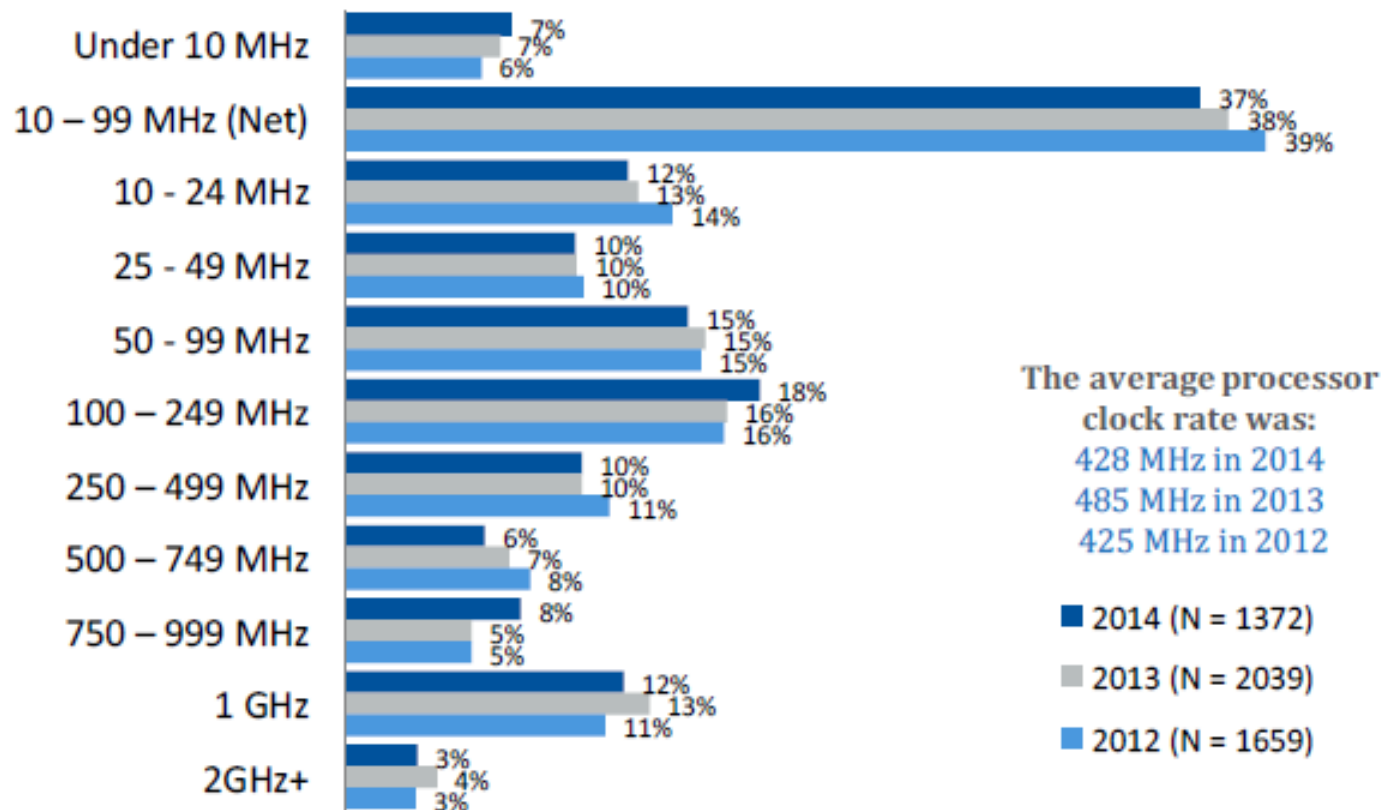
# 2014 Embedded Market Study

- current main processor size:



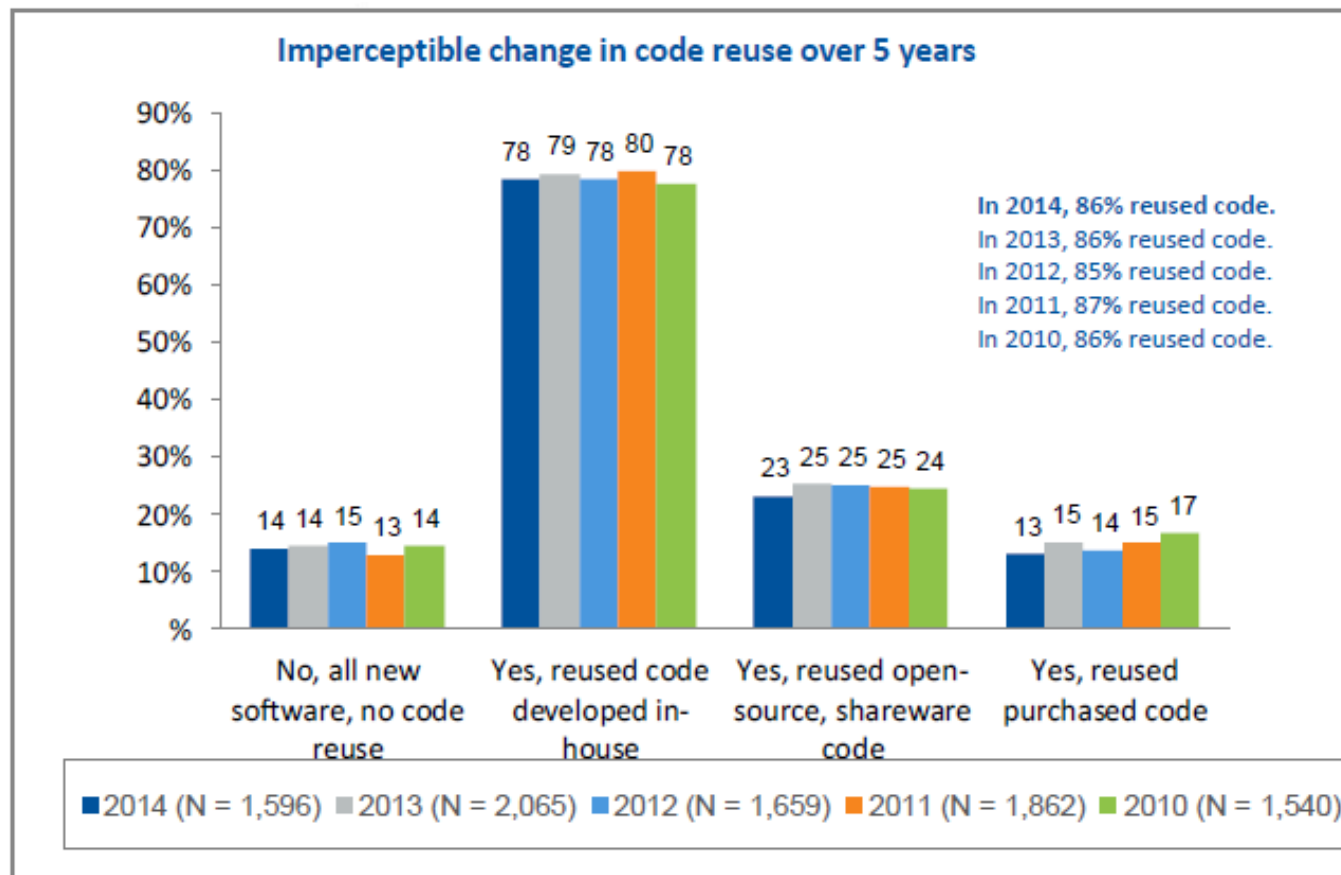
# 2014 Embedded Market Study

- current main processor clock rate:



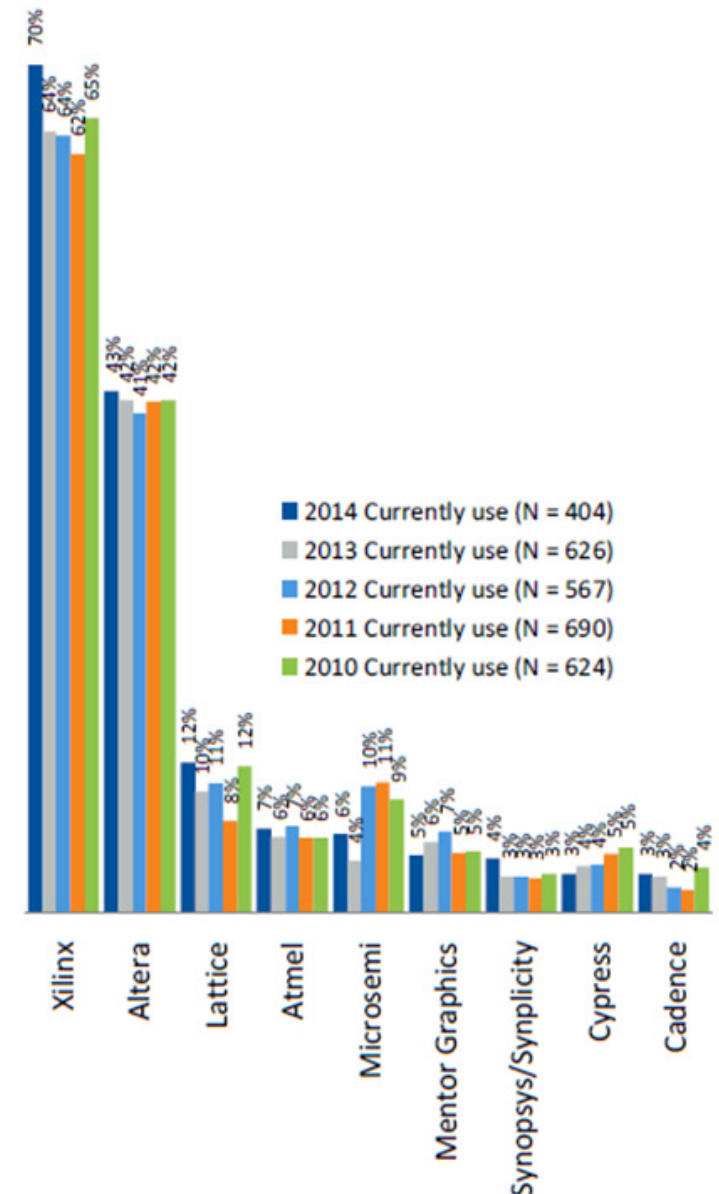
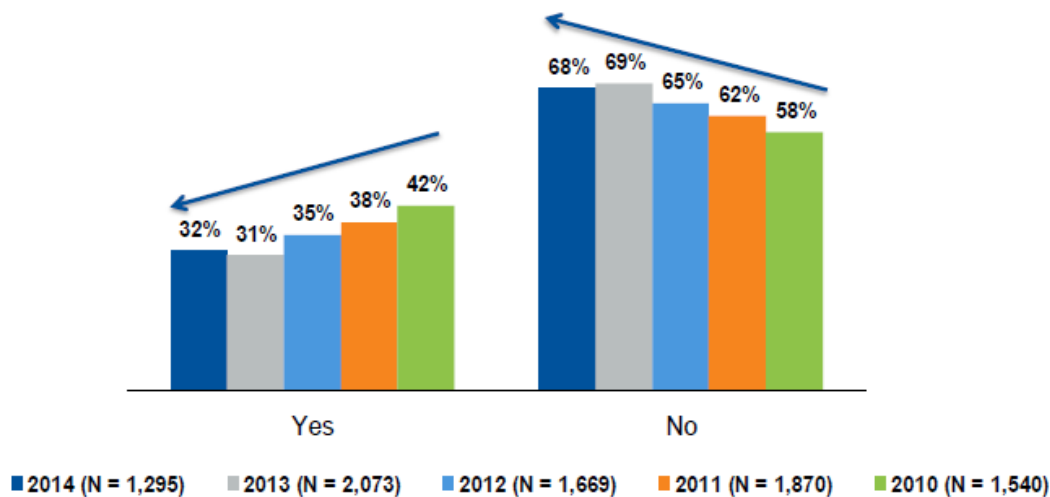
# 2014 Embedded Market Study

- Do you reuse code?




# 2014 Embedded Market Study

- Does current design use programmable logic?
- If so, which vendor?

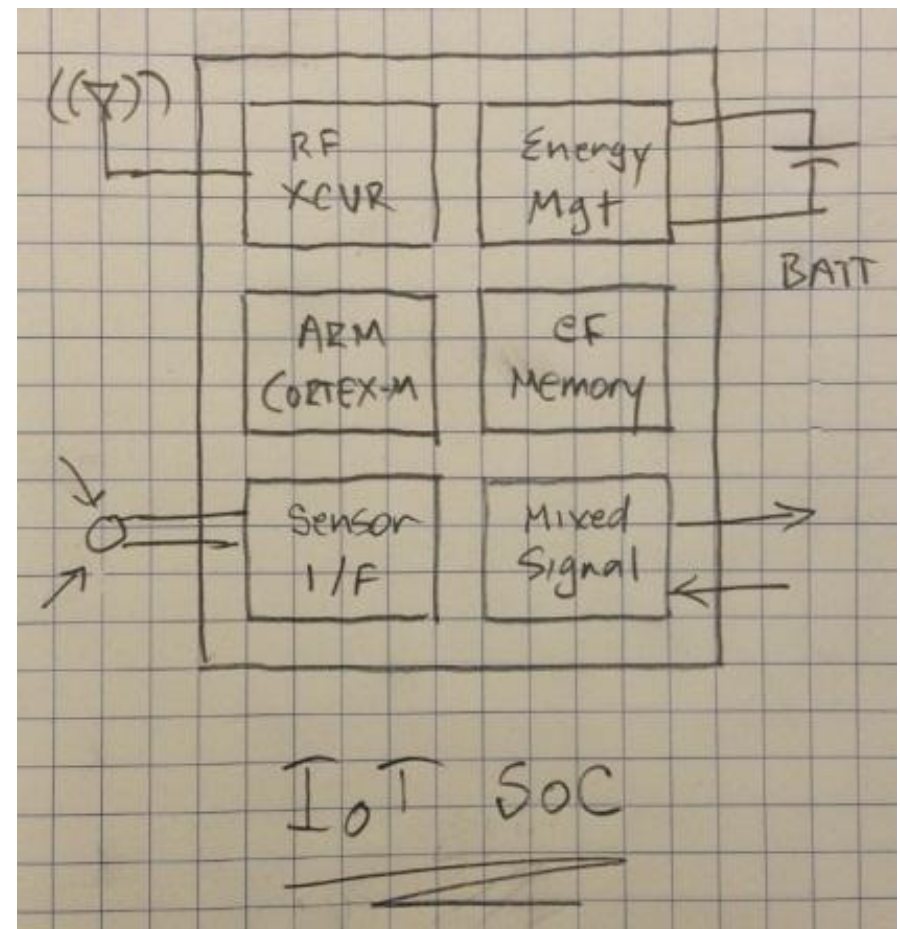


# 2014 Embedded Market Study

- Programmable Logic: Key Messages
    - FPGA usage is trending steadily **downward**
      - 45% six years ago to 32% this year.
      - may indicate a pause in the trend
    - Gradual decline of FPGAs/programmable logic usage in **upcoming** embedded projects:
      - 60% said “yes” in 2005, down to 41% in 2014
    - Not needing the functionality, cost and difficulty programming are the main reasons for not using customizable chips/FPGAs.
- 

# Future Drivers - the IoT?

- Sensor interface
- low-energy microcontrollers
  - 8 – 32 bit
- wireless technology
  - ZigBee
  - 802.15.4 (various flavors)
  - Bluetooth low-energy solution (BLE)
  - proprietary standards
- Energy management
- memory

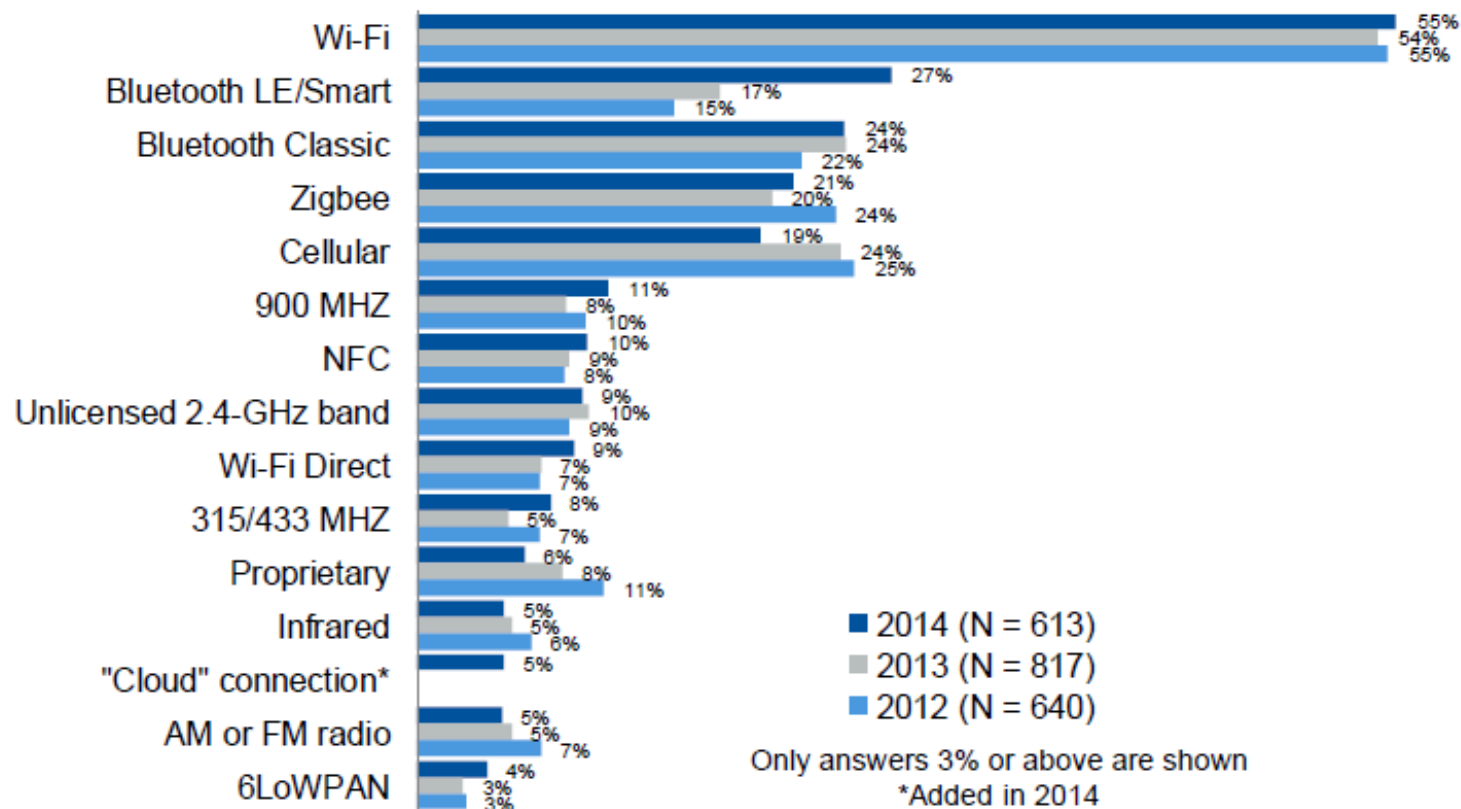


Source: [http://www.eetimes.com/document.asp?doc\\_id=1321706](http://www.eetimes.com/document.asp?doc_id=1321706)

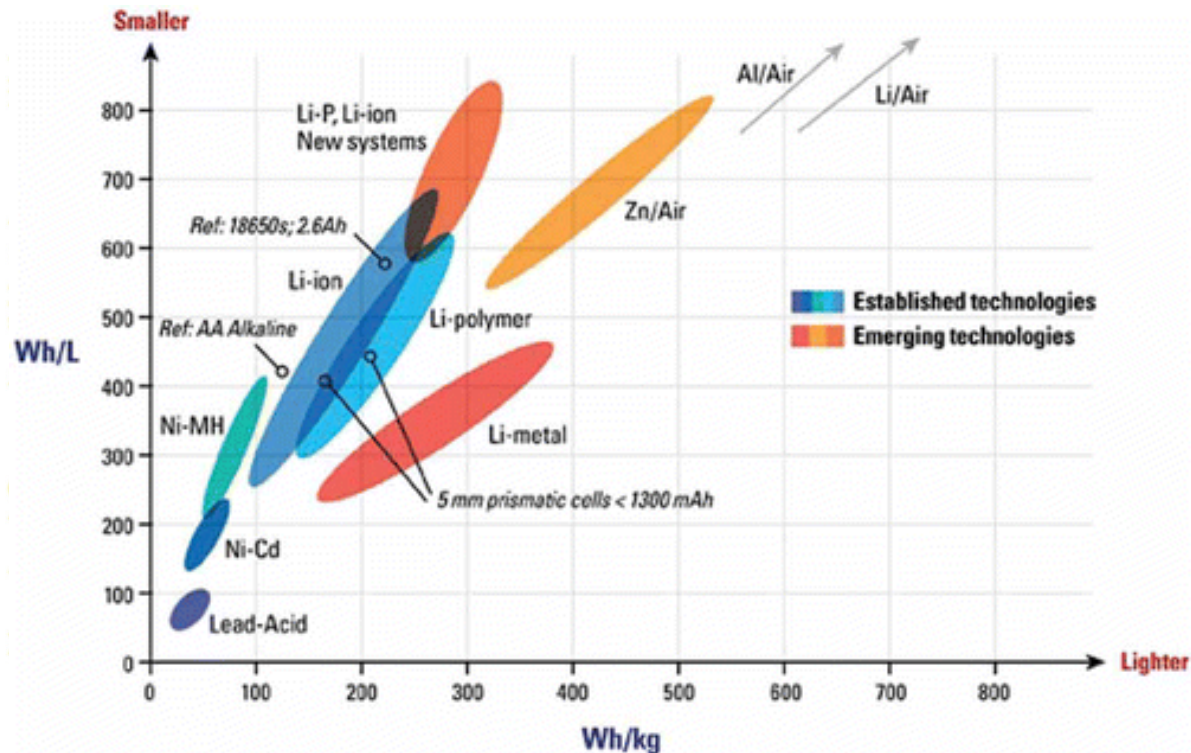
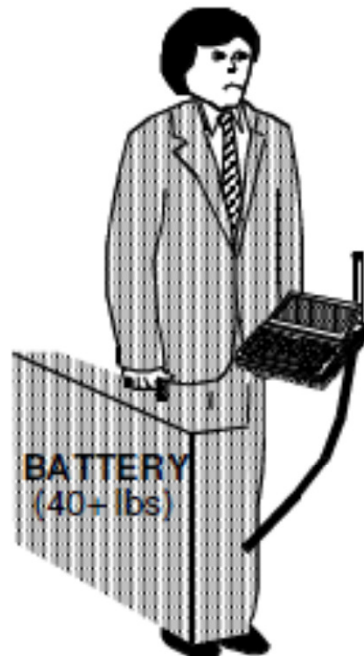


# 2014 Embedded Market Study

- Wireless Designs



# Future Drivers - Energy



Multimedia Terminals

Laptop Computers

Digital Cellular Telephony

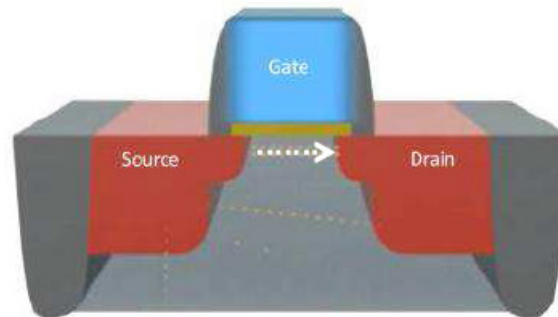
Expected Battery Lifetime increase  
over next 5 years: 30-40%

Portability

# Future Drivers - Technology

- Mixed RF/Analog/Digital

- 28 nm Bulk Transistor

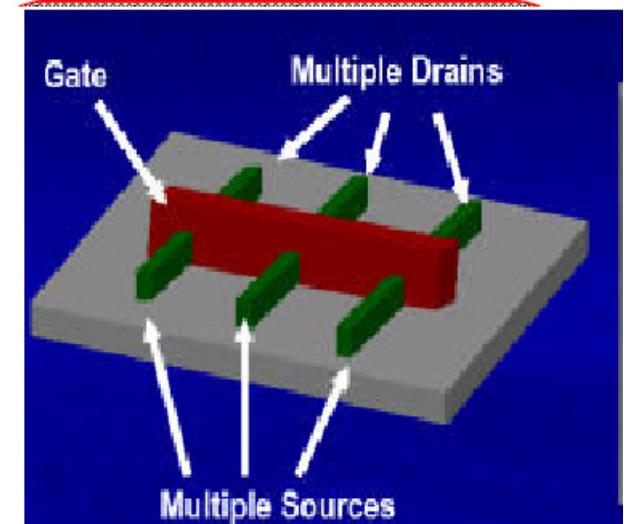
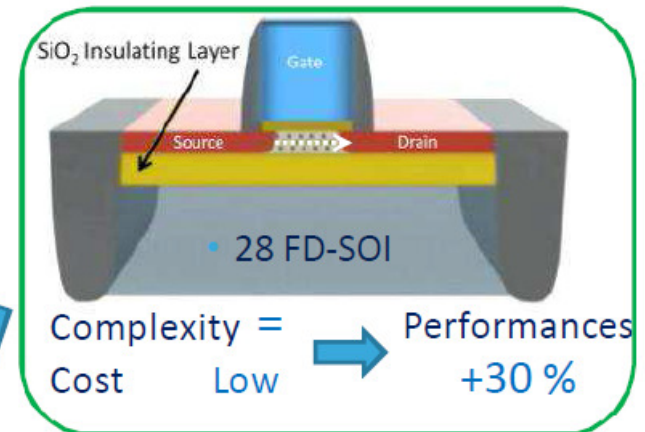


- 20 nm Bulk Issue:

Complexity ↑  
Cost ↑ → Performances ~ +10 %

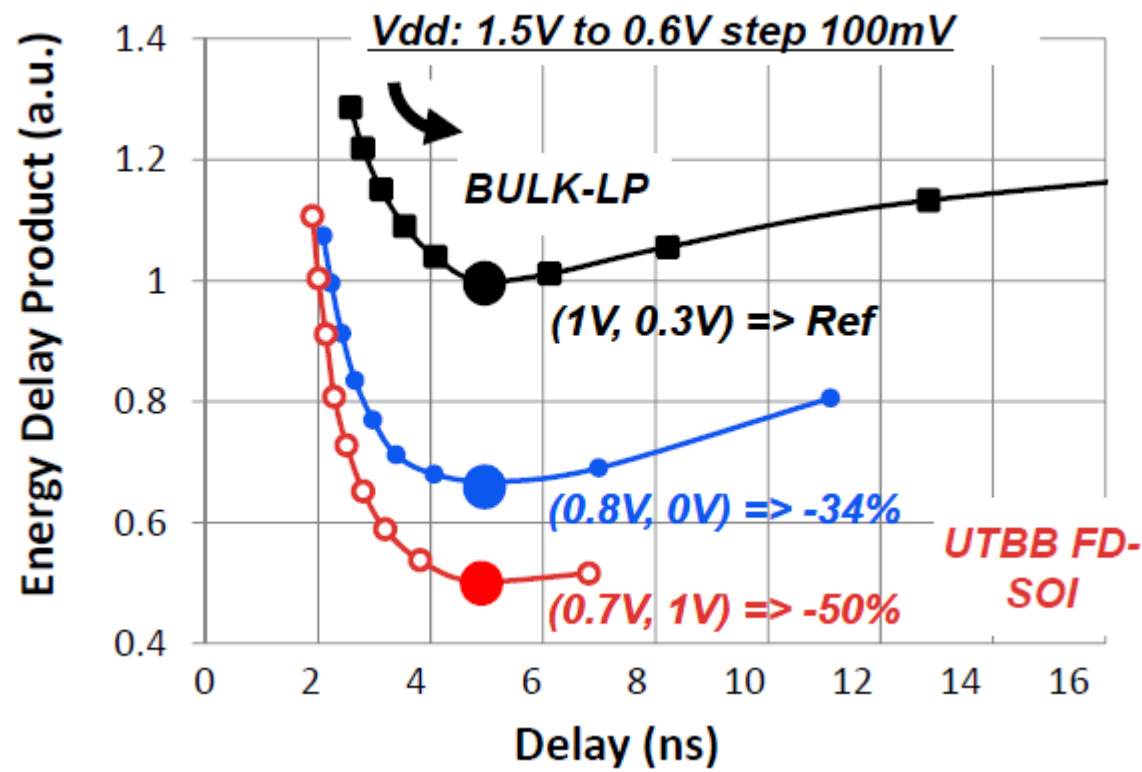
FD-SOI  
(2D)

TriGate  
FinFET  
(3D)



# Future Drivers - Technology

- UTBB-FDSOI - Energy Efficiency

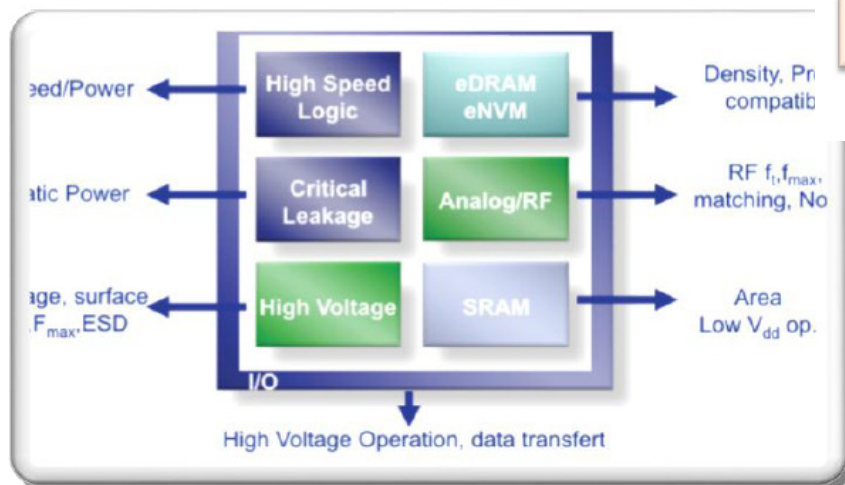


# Future Drivers – 3D Packaging

- 3D Stacking Technology

## 2D SOC

“All-in-One chip system integration”

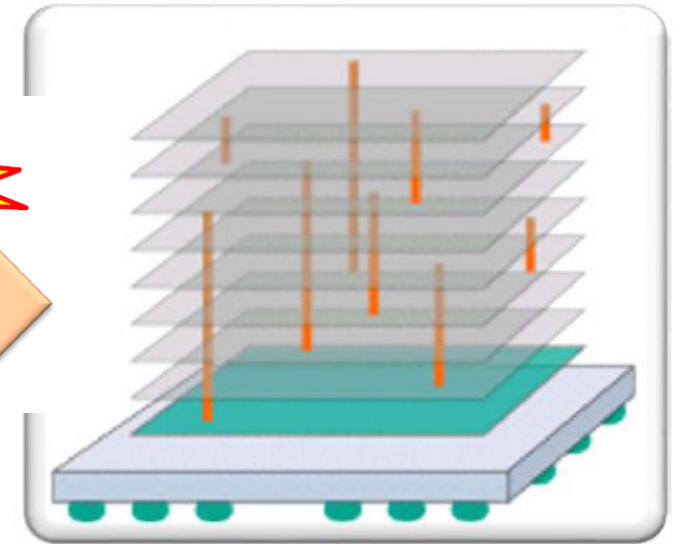


**2.5D?**

Evolution  
or Revolution?

## 3DIC / 3D SoC

“De-integrated & Re-integrated SOC”



All functions on 28nm lithography

→ Chip area ↑, Cost ↑

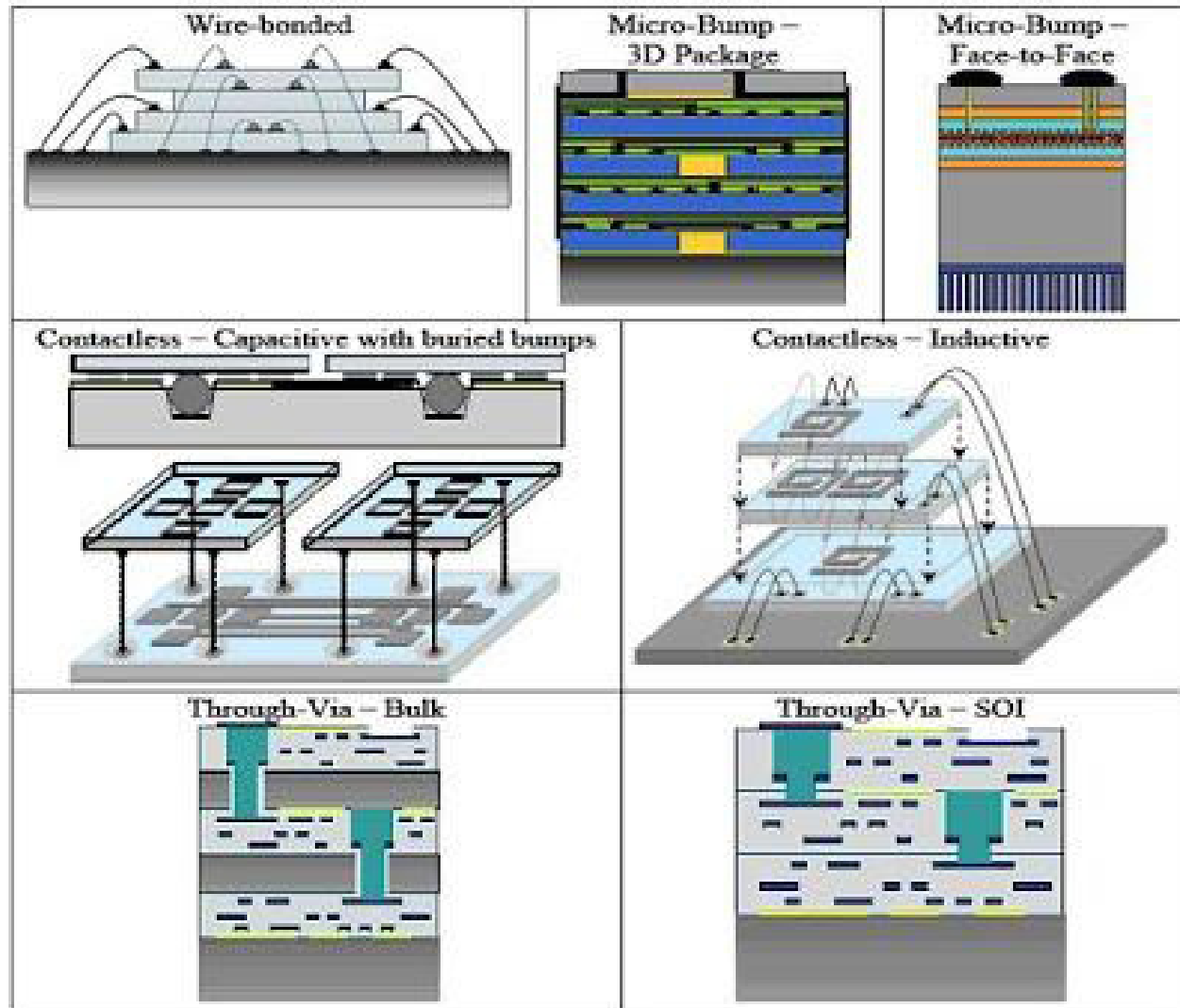
<b>MEMS</b>	130 nm	200 mm
<b>Memory</b>	45 nm	300 mm
<b>Logic</b>	22 nm ?	450 mm ?
<b>Analog</b>	90 nm	300 mm

Source: Yole, 2.5D, 3DIC &  
TSV Interconnects Patent Analysis, May 2013



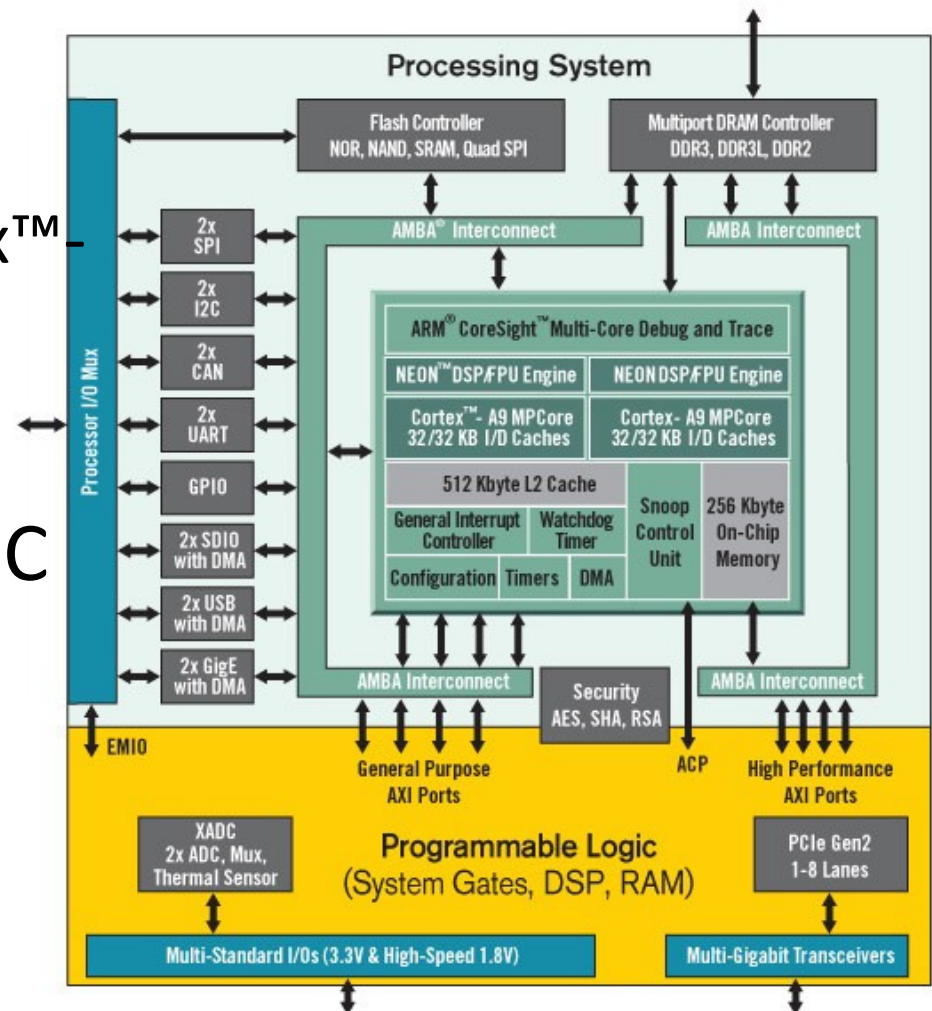
# Future Drivers – 3D

- 3D stacking methods

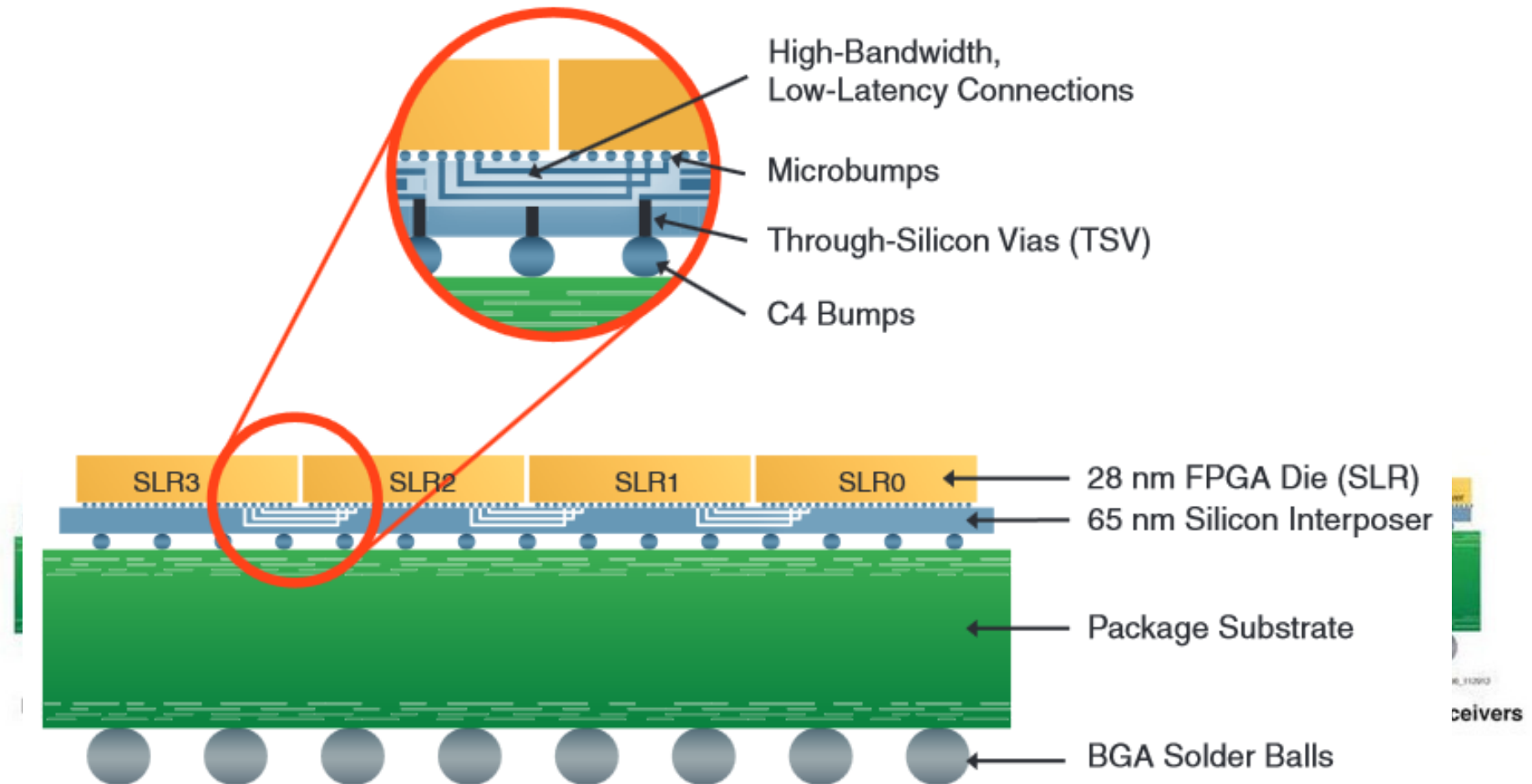


# Recent Examples - Xilinx

- Zynq-7000
  - ARM® dual-core Cortex™ A9 processors
  - Programmable logic
- Zynq UltraScale+ MPSoC
  - Quad-core Cortex A53
  - Peripherals
  - Programmable Logic



# Recent Examples - Xilinx



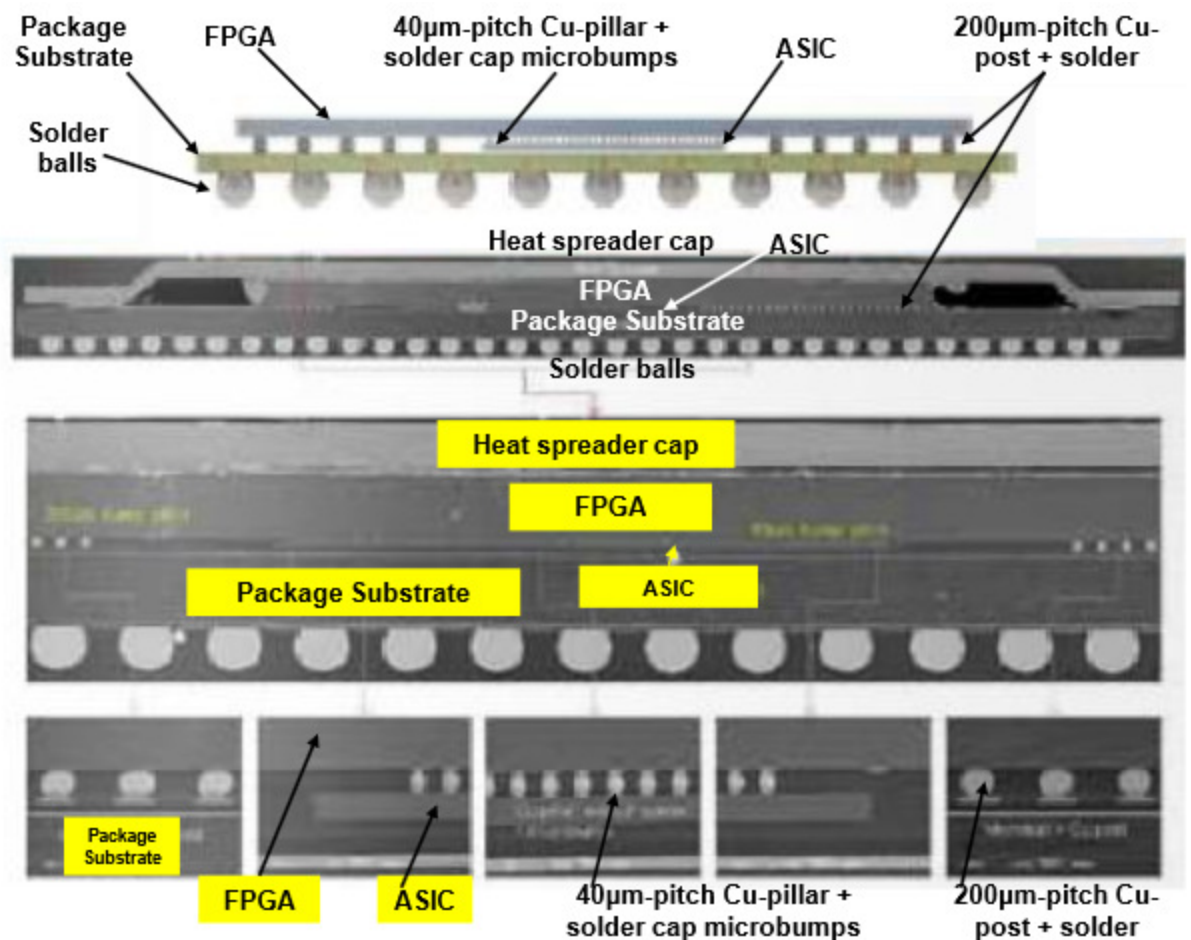
Source: <http://www.xilinx.com/products/silicon-devices/3dic.html>



# Recent Examples - Altera

- *AMCOR “POSSUM” process*

- *multi-stacked die without TSVs*
- *daughter die mounted face to face with mother die then mounted onto a substrate*

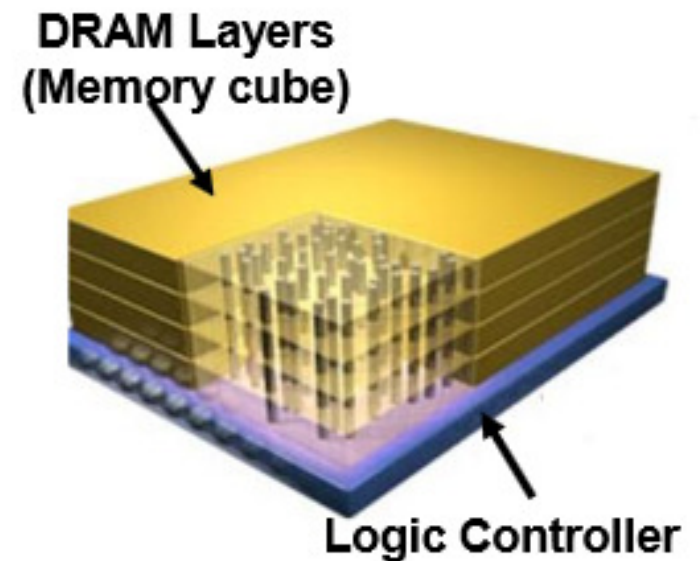


Source: [http://s3.amazonaws.com/sdieee/1817-SanDiego/CPMTDL\\_Lau\\_advancedpackaging.pdf](http://s3.amazonaws.com/sdieee/1817-SanDiego/CPMTDL_Lau_advancedpackaging.pdf)

# Hybrid Memory Cube (HMC)

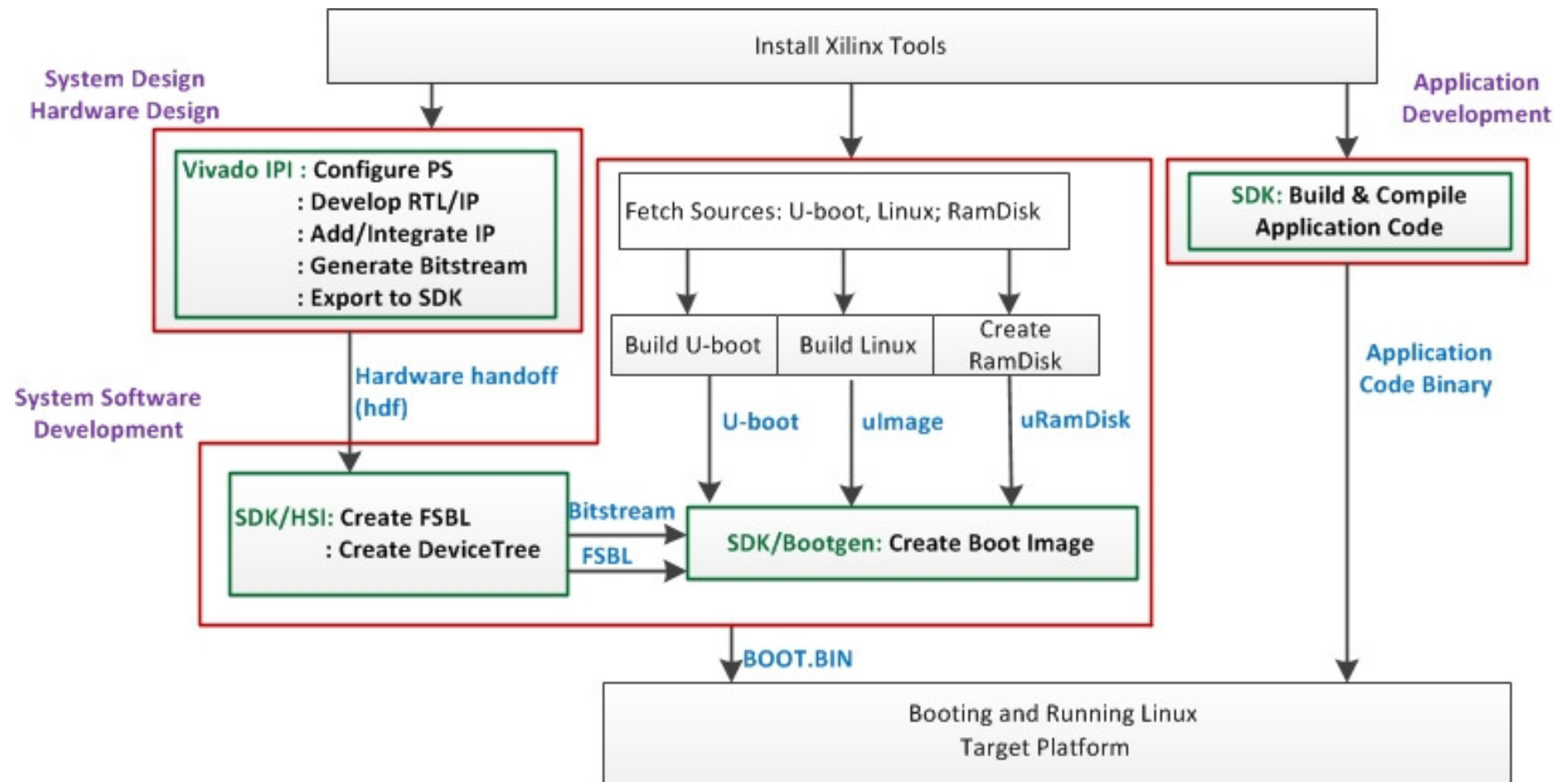
The HMC consortium already has 8 members:

- ◆ Micron
- ◆ Samsung
- ◆ Altera
- ◆ ARM
- ◆ IBM
- ◆ Open-Silicon
- ◆ SK Hynix
- ◆ Xilinx



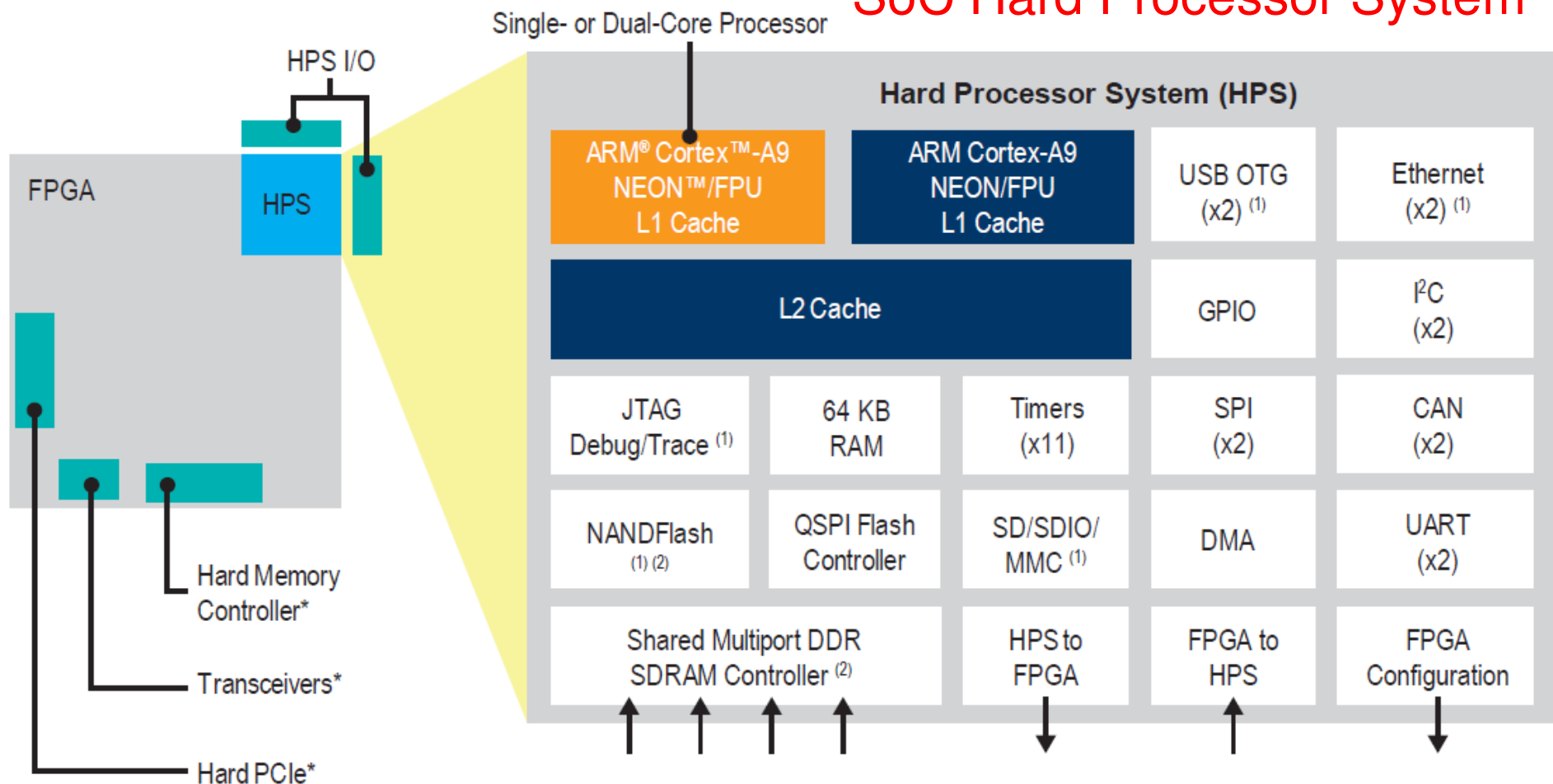
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# Xilinx Design Flow



# Recent Examples - Altera

## SoC Hard Processor System



\*Optional Configuration <sup>(1)</sup> Integrated DMA <sup>(2)</sup> Integrated ECC



DS-5 Debug - HPS/linux-bringup/drivers/gpio/gpio-altera.c - Eclipse Platform

File Edit Source Refactor Navigate Search Project Run Window Help

Debug Cont Project Expl Remote Sys

Altera SoC FPGA connected

Active Threads

- blinky #4 stopped on breakpoint #2 (PID 481 v)
  - arch\_local\_irq\_save
  - altera\_gpio\_set+0x8
  - gpio\_set\_value\_cansleep+0x6C
  - gpio\_value\_store+0xC0
  - dev\_attr\_store+0x18
  - flush\_write\_buffer+0x40
  - sysfs\_write\_file+0x108
  - vfs\_write+0xA4
  - sys\_write+0x40
  - ... (truncated)

Altera SoC FPGA connected

Commands History Scripts

Linked: Altera SoC FPGA

```
wait
continue
Execution stopped at breakpoint 2: S:0x7F000038
In thread 2 (OS thread id 479)
S:0x7F000038 85,0 {
wait
continue
Execution stopped at breakpoint 2: S:0x7F000038
In thread 3 (OS thread id 478)
S:0x7F000038 85,0 {
wait
continue
Execution stopped at breakpoint 2: S:0x7F000038
In thread 4 (OS thread id 481)
S:0x7F000038 85,0 {
```

Command: Press (Ctrl+Space) for Content Assist Submit

Breakpoints Expressions f() Functions

Linked: Altera SoC FPGA

Name	Start Address
altera_gpio_get	S:0x7F000000
altera_gpio_set	S:0x7F000038
altera_gpio_dir_in	S:0x7F000068
altera_gpio_dir_out	S:0x7F00009C
altera_gpio_save_regs	S:0x7F0000F0

Variables

Linked: Altera SoC FPGA

Name	Value	Type	Count	Size	Location
Locals	1 variable				
flags	27	long unsigned int		32	\$R3
File Statics (current)					
Globals	954 variables				

gpio-altera.c

```
78 * @gpio: GPIO signal number.
79 * @val: Value to be written to specified signal.
80
81 * This function writes the specified value in to the
82 * GPIO device.
83 */
84 static void altera_gpio_set(struct gpio_chip *gc, unsigned long flags;
85 {
86     struct of_mm_gpio_chip *mm_gc = to_of_mm_gpio_chip(gc);
87     struct altera_gpio_instance *chip = to_altera_gpio_instance(gc);
88
89     spin_lock_irqsave(&chip->gpio_lock, flags);
90
91     /* Write to shadow register and output */
92     if (val)
93         chip->gpio_state |= 1 << gpio;
94     else
95         chip->gpio_state &= ~(1 << gpio);
96     __raw_writel(chip->gpio_state, mm_gc->regs + ALTE
97
98     spin_unlock_irqrestore(&chip->gpio_lock, flags);
99 }
100
101
102 /*
```

Disassembly

Linked: Altera SoC FPGA

Address	Opcode	Disassembly
S:0x7F000024	15903050	LDRNE r3,[r0,#0x50]
S:0x7F000028	E5933000	LDR r3,[r3,#0]
S:0x7F00002C	E1A01133	LSR r1,r3,r1
S:0x7F000030	E2010001	AND r0,r1,#1
S:0x7F000034	E12FFF1E	BX lr
S:0x7F000038	E10F3000	altera_gpio_set
S:0x7F00003C	F10C0000	MRS r3,APSR ; forme
S:0x7F000040	E3A0C001	CPSID i
S:0x7F000044	E3520000	MOV r12,#1
S:0x7F000048	E5902054	CMP r2,#0
S:0x7F00004C	1182111C	LDR r2,[r0,#0x54]
S:0x7F000050	01C2111C	ORRNE r1,r2,r12,LSL r
S:0x7F000054	E5902050	BICEQ r1,r2,r12,LSL r
S:0x7F000058	E5801054	LDR r2,[r0,#0x50]
S:0x7F00005C	E5821000	STR r1,[r0,#0x54]
S:0x7F000060	E121F003	STR r1,[r2,#0]
S:0x7F000064	E12FFF1E	MSR CPSR_c,r3
S:0x7F000068	E52D4004	BX lr
S:0x7F00006C	E52D4004	altera_gpio_dir_in
S:0x7F000070	E52D4004	PUSH {r4}

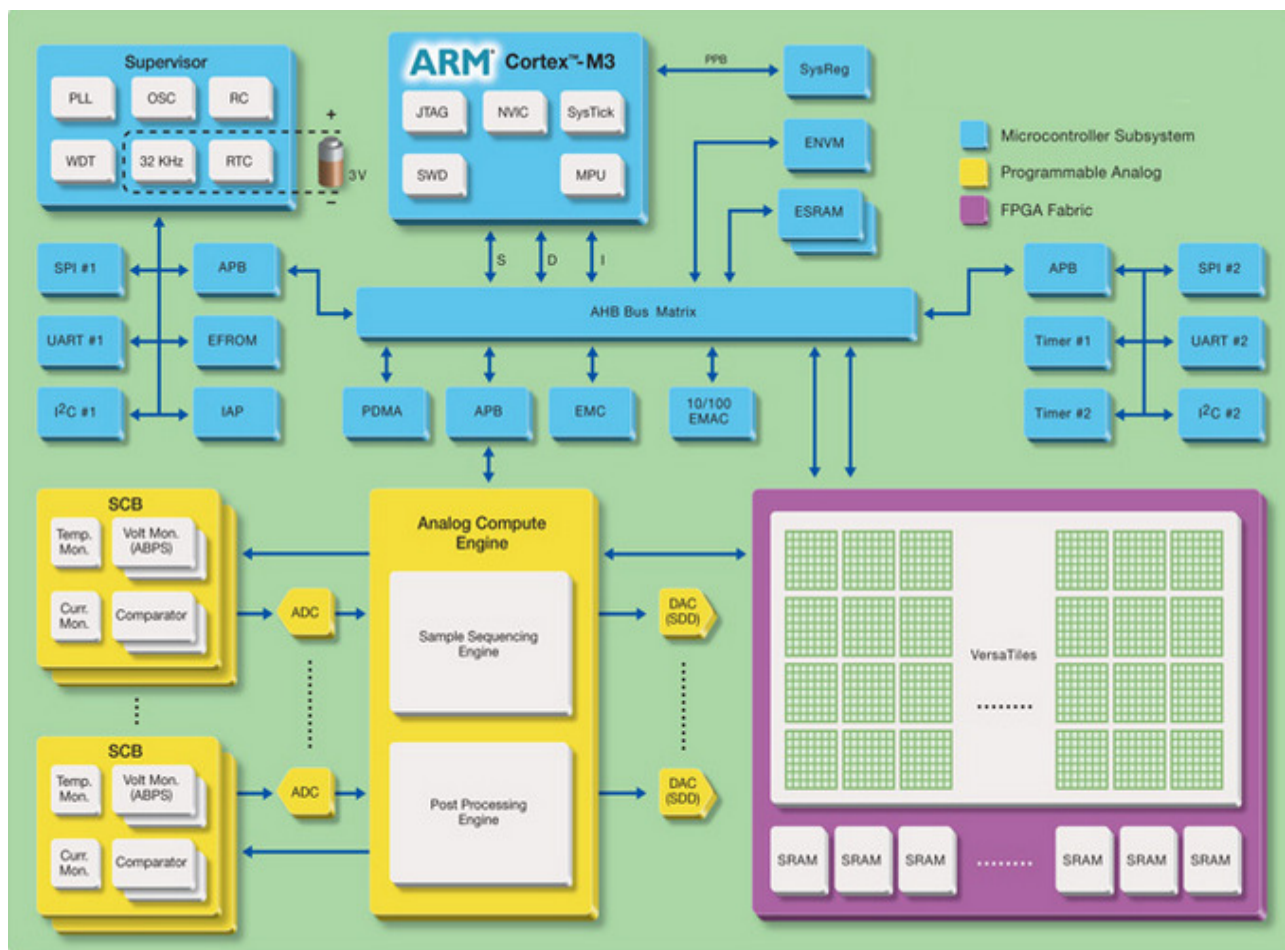
Linked: Altera SoC FPGA

Name	Value	Size	Access
sptimer0			
sptimer1			
stm			
sysmgr			
uart0			
uart1			
usb0			
usb1			
PIO_inst_0			
PIO_inst_0_DATA	0x0000000E	32	R/W
PIO_inst_0_DIRECTION	0x00000000	32	R/W
PIO_inst_0_IRQ_MASK	0x00000000	32	R/W
PIO_inst_0_EDGE_CAP	0x00000000	32	R/W
PIO_inst_0_SET_BIT	write only	32	WO
PIO_inst_0_CLEAR_BITS	write only	32	WO
UART_inst_0			
JTAG_UART_inst_0			
SYSID_inst_0			

Writable Smart Insert 86 : 25

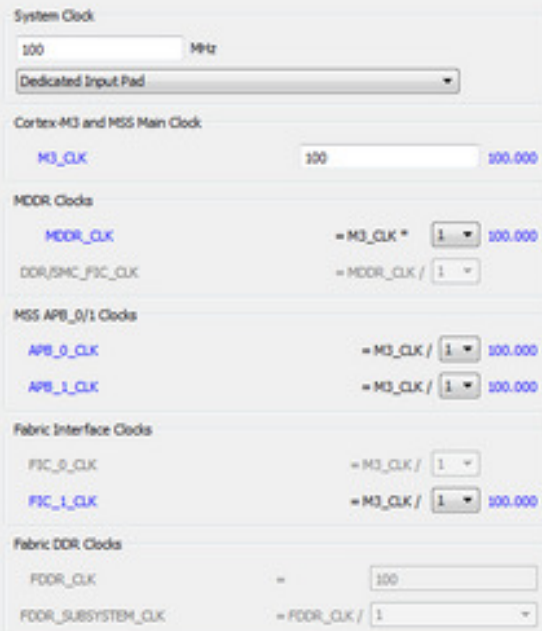
# Recent Examples - MicroSemi

## SmartFusion System-on-Chip FPGA



- Hard 32-bit ARM Cortex-M3 microcontroller
- Programmable analog
  - ADC/DAC
  - Comparators
  - Analog computation
- voltage/current/temperature monitors,
- FPGA fabric

## System Builder - Clock Settings





# Some Final Words

XCELLENCE IN VIDEO PROCESSING

## 4K TV Development Made Easy with the Zynq SoC

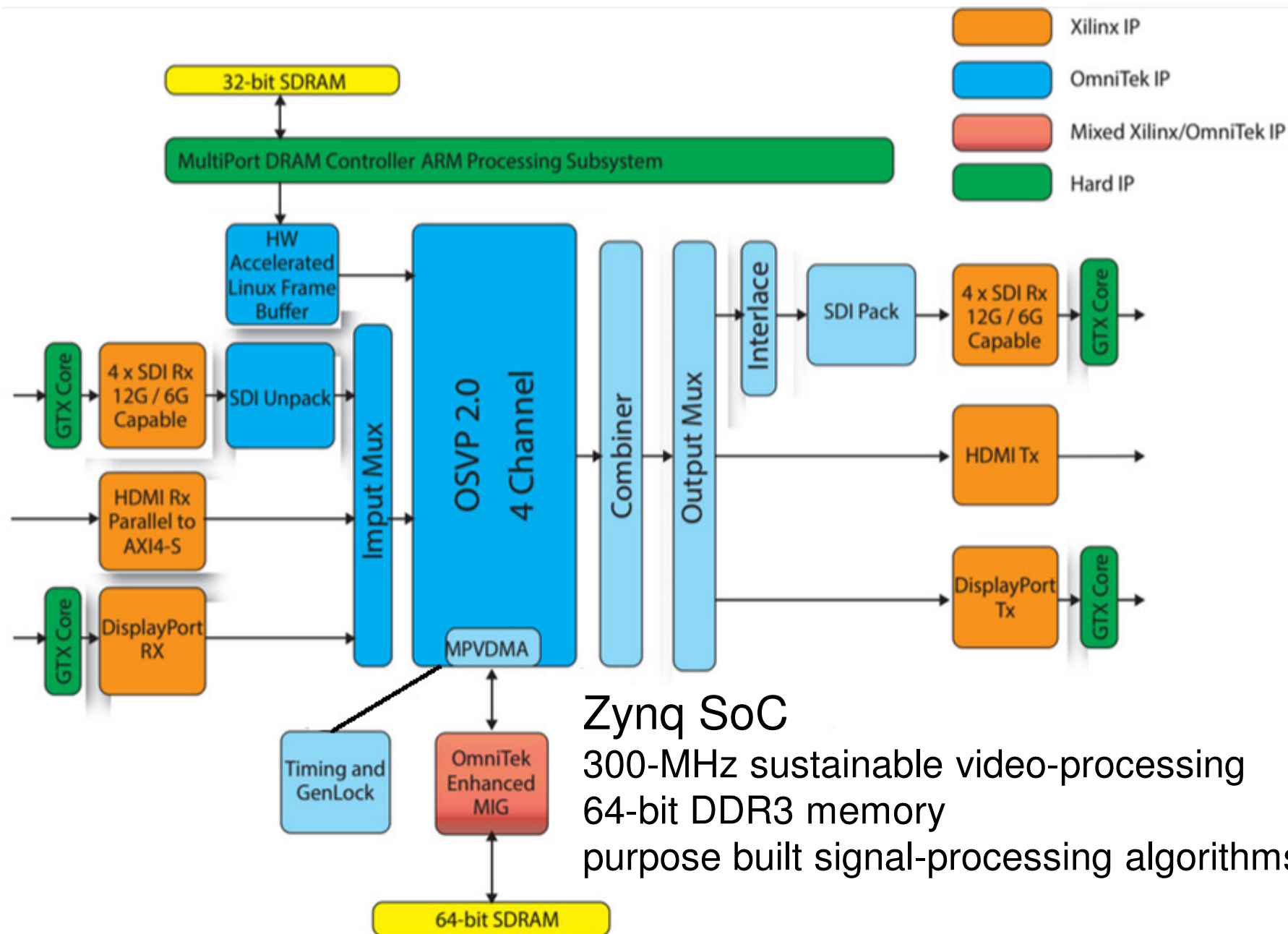
**by Roger Fawcett**

Managing Director

OmniTek

[roger.fawcett@omnitek.tv](mailto:roger.fawcett@omnitek.tv)





## Zynq SoC

300-MHz sustainable video-processing  
64-bit DDR3 memory  
purpose built signal-processing algorithms

https://www.skatelescope.org/blog/kermode-fpga-board/ LT1328

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## Kermode FPGA Board

Testing of NRC's Kermode FPGA board is nearly complete. The board is being developed for the Advanced Focal Array Demonstrator (AFAD) and is well suited to SKA1-scale beamforming, correlation, as well as other I/O intensive signal processing.

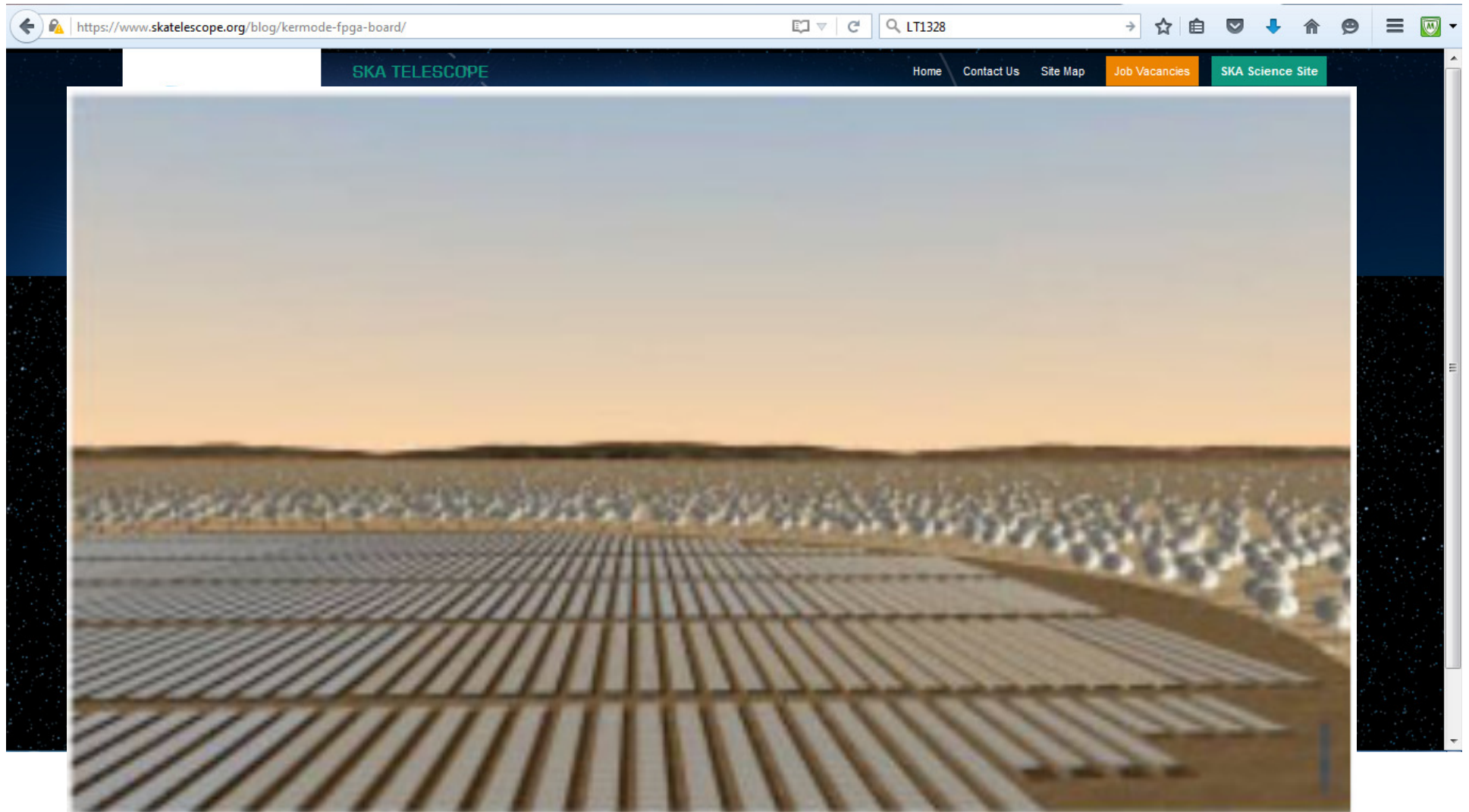


Based on the Industry Standard AdvancedTCA platform, each board has eight Xilinx V6-SX475 FPGAs each with two 4GB memories. The total I/O data rate is 1200 Gpbs via the Zone 3, 2 and four front panel FCM connectors. The board will soon be available commercially through Nutaq, and uses their board support development kit to facilitate rapid development. For

more information contact [Gary.Hovey@nrc.ca](mailto:Gary.Hovey@nrc.ca)

f 0 g+ 0 in 0 t 0 e

- 8 Xilinx V6-SX475 FPGAs
  - each with two 4GB memories
- total I/O data rate: 1200 Gpbs



- each with two 4GB memories
- total I/O data rate is 1200 Gpbs

## Conclusions – my guesses

- SoC design is hard – and getting harder
  - Tools try to help but still limited
- FPGA usage is trending steadily downward
  - My guess is because of perceived design difficulty combined with ease of software reuse
- Complex programmable SoC devices (e.g. Zynq) may struggle in the IoT space
  - Due to cost & power issues
  - But might be OK due to flexibility and time to market



# Recent Trends in System On Chip Modeling

